

GE Mobile Communications



MPI PERSONAL RADIO

403-512 MHz PERSONAL RADIO 2/4 WATTS

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COMBINATION NOMENCLATURE

DIGITS 1&2	DIGIT 3	DIGIT 4	DIGIT 5	DIGIT 6	DIGIT 7	DIGIT 8	DIGIT 9
Product Code	Package	TX Frequency Range	RX Frequency Range	Channel Spacing	RF Power Output	Max. Channel Capacity	Control
P5	Local/ Remote	403-425 MHz	403-425 MHz	5 25 KHz	5 1.7-3.8 Watts	B 2 Tx-2 Rx	E Standard
•		420-450 MHz	420-450 MHz		3.9-6.4 Watts	2 Tx-1 Rx	
		R 450-470 MHz	R 450-470 MHz			1 Tx-2 Rx	•
		\$ 470-494 MHz	470-494 MHz				
		489-512 MHz	489-512 MHz			RC512	1 .

STRUCTURED OPTIONS

Option TX Xtals	B Option RX Xtals	C	D Option	Option	Option	Option	K Alt IF
A 1 Xtal	A 1 Xtal	None	None	None	None	None	None
B 2 Xtals	B 2 Xtals	2 1 Tone Enc CG	T-99 Ind.	DTMF	4 Int. Safe	A CGE UHF	3 Alt IF
O No Xtals	O No Xtals	1 Tone/Enc DCG	T-99 IndGroup			B CGE HB	
		1 Code Enc. DCG.	T-99 Ind. CG Enc				
· · · · · · · · · · · · · · · · · · ·		1 Code Enc/ Dcc DCG			•		
· · .		R 1 Tone CG Enc w/Switch			RC4	1345A Sheet 2	
	·.	1 Tone DCG Enc w/Switch					•

TYPICAL SPECIFICATIONS* SYSTEM

FCC IDENTIFICATION NUMBER

2-WATT

4-WATT

AXA9MZTR102A-450-512 MHz AXA9MZTR121A-450-470 MHz AXA9MZTR121B-470-494 MHz

AXA9MZTR121C-489-512 MHz

FREQUENCY RANGE

403-512 MHz

BATTERY DRAIN (MAXIMUM)

Receiver Standby

Rated Audio

15 milliamperes 150 milliamperes

Transmitter

800 milliamperes @ 7.5 Volts (2-Watt) 1250 milliamperes @ 10 Volts (4-Watt)

7.81 on 4-Watt

TEMPERATURE RANGE

-30 °C (-22 °F) to +60 °C (140 °F)

DIMENSIONS (EIA) LESS ACCESSORIES

(H X W X D)

7.11 x 2.59 x 1.46 inches

 $(180.5 \times 65.7 \times 37.1 \text{ millimeters})$

WEIGHT, WITH ANTENNA

2-Watt 455 grams (16 ounces) 4-Watt 492 grams (17.3 ounces)

BATTERY LIFE

At 5% - 5% - 90% Duty Cycle At 2% - 8% - 90% Duty Cycle

2-Watt 8 hours 12 hours 4-Watt 6.5 hours 11 hours

TRANSMITTER

POWER OUTPUT

2 Watts/4 Watts

FREQUENCY STABILITY 0.0005%

CONDUCTED SPURIOUS
AND HARMONIC EMISSION

RATED SYSTEM DEVIATION

±5 kHz

FM HUM & NOISE

Greater than 50 dB

AUDIO PREQUENCY CHARACTERISTICS FCC and EIA. Frequency Response per EIA RS 316-B. Post limiter filter per

DISTORTION DEVIATION SYMMETRY Less than 5% (300 to 3000 Hz)

DEGRADATION DEGRADATION DEGRADATION

10 MHz

MAXIMUM FREQUENCY SPREAD RF OUTPUT IMPEDANCE

50 oh

RECEIVER

AUDIO OUTPUT (to 8.0 ohm speaker)

500 milliwatts (less than 5%

SENSITIVITY 12 dB SINAD 20 dB Quieting

FREQUENCY STABILITY

SELECTIVITY

EIA Two-Signal Method

0.0005%

-70 dB @ +25 kHz

SPURIOUS RESPONSE

-60 dB

INTERMODILLATION MODULATION ACCEPTANCE -65 dB

SQUELCH SENSITIVITY

±6.7 kHz <6 dB SINAD

FREQUENCY RESPONSE

EIA RS 316-B

MAXIMUM FREQUENCY SPREAD

RF INPUT IMPEDANCE

DEGRADATION

These specifications are intended primarily for use of the serviceman. Refer to the appropriate Specifications Sheet for the complete specifications.

DESCRIPTION

General Electric MPI Personal radios are extremely compact, high performance two-way FM radios designed for operation in the 403-512 MHz range. The light-weight radio utilizes both discrete components and Integrated Circuit modules (IC's).

All operating controls except the Push-To-Talk (PTT) switch and frequency select switch are conveniently located on the top of the radio. The frequency select and PTT switches are located on the side of the radio. An earphone jack, located above the PTT switch, is used with an earphone to provide message privacy, or to permit the operator to receive messages in noisy locations.

An external microphone jack is located next to the earphone jack. This permits the transmitter to be keyed and messages transmitted using the external microphone.

Power for the radio is supplied by a rechargeable nickel-cadmium battery pack that fits in the bottom front section of the case. The battery pack can be recharged either in or out of the radio.

Test Adaptor 4EX12A12 is available to provide audio connections for servicing the transmitter and receiver.

OPERATION

If the radio is equipped with an option switch, disable the option before adjusting the radio by placing the switch in the OFF or MONITOR position. After adjusting the radio, place the option switch back in the CG OR T99 position (See Figure 1).

ADJUSTING THE RADIO

To Receive a Message:

1. Turn the OFF-VOLUME control about half way to the right.

- Disable any option by placing the option control toggle switch (if present) in the OFF or MONI-TOR POSITION.
- 3. Turn the SQUELCH (SQ) control to the right as far as possible. A hissing sound will be heard from the speaker.
- 4. Adjust the VOLUME control until the hissing sound is easily heard but not annoyingly loud.
- 5. Turn the SQUELCH control slowly to the left until the hissing noise just stops. This adjustment is very important as it eliminates annoying noise when no one is calling you. It also determines how sensitive your radio will be to incoming calls.
- 6. In two-frequency units, select the proper frequency. You are now ready to receive messages from other radios in your system.

To Send a Message:

- Turn on the radio as directed in the "To Receive a Message" section.
- In two-frequency units, select the proper frequency. Then listen to make sure that no one is using the channel.
- 3. Hold the radio so that the antenna is vertical. Then, press the Push-To-Talk (PTT) bar and speak directly into the microphone in a clear and distinctive voice. Always release the PTT bar as soon as you stop talking. You cannot receive messages while the PTT bar is pressed.

CHARGERS

Three battery chargers are available for recharging the Nickel-Cadmium battery pack. For specific instructions, refer to the applicable operating instruction or maintenance manual.

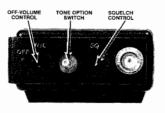
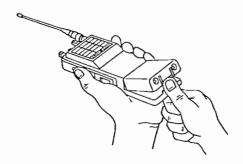


Figure 1 - Operating Controls

BATTERY PACK REPLACEMENT

To remove the battery pack from the radio:

- 1. Turn the radio OFF.
- Place thumb on bottom of battery pack and press battery pack to-ward the top of radio as shown.
- 3. Then push bottom of battery pack away from the radio.



- WARNING

Do not dispose of battery packs or batteries by burning. To do so may cause an explosion.

OSCILLATOR CRYSTAL REPLACEMENT

Crystals Y1, Y2, Y4, and Y5 are plug-in types for ease of replacement. Note that one lead is grounded to the crystal can. This lead must be plugged into the socket which is connected to the ground plane of the Transmit/Receive Board.

CIRCUIT ANALYSIS

TRANSMITTER

The Transmitter is a crystal-controlled, frequency modulated transmitter for one- or two-frequency operation in the 403-512 MHz bands. The transmitter utilizes discrete components to provide a minimum RF power output of two watts. The transmitter consists of the following assemblies.

- Audio Board with the microphone amplifier/limiter, postlimiter filter and oscillator compensator circuits.
- Transmit/Receive (TR) Board -Oscillator, Multiplier stages, amplifier, driver and PA stages, TR switch, and low-pass filter.

All supply voltages for the transmitter are provided by the battery and the Regulator. The different transmitter voltages required are shown in the following chart:

Voltage	Used For
Continuous 10/7.5 Volts	Post-limiter filter, driver and PA circuits
Switched TX 10/7.5 Volts	Multipliers, 1st am- plifier, and driver base voltage
Switched TX 5.4 Volts	Mic amp/limiter, mi- crophone and oscil- lator
Regulated 5.4 Volts	Compensator and modu- lator circuits

References to symbol numbers mentioned in the following text are found on the Schematic Diagrams, Outline Diagrams and Parts List. A block diagram of the complete transmitter and receiver is shown in Figure 2.

AUDIO CIRCUITS

Audio from the microphone is applied to a 6 dB pre-emphasis network (R16, D1, C15 and C18) and then to amplifier-limiters Q3 and Q4. The output of Q4 is applied to the post-limiter filter consisting of Q6, Q7, Q8 and associated circuitry.

The output of the post-limiter filter is coupled through C30 and the modulation circuitry to transmitter oscillator Q15.

A compensator circuit (Q9 and R36 through R40) provides frequency compensation at low temperatures for the transmitter and receiver oscillators.

T/R BOARD

OSCILLATOR

The temperature compensating DC voltage and audio is applied to FM modulators D6 and D7 through MOD ADJ controls R67 and R73. The modulator varactor varies the transmit frequency at the audio rate applied from the audio board.

Q15, Y4, Y5 and associated circuitry comprise a Colpitts oscillator. The transmit oscillator is adjusted to the assigned operating frequency by L39 and L42. The oscillator output is applied to buffer Q14. Channel 1 or Channel 2 is selected by S2.

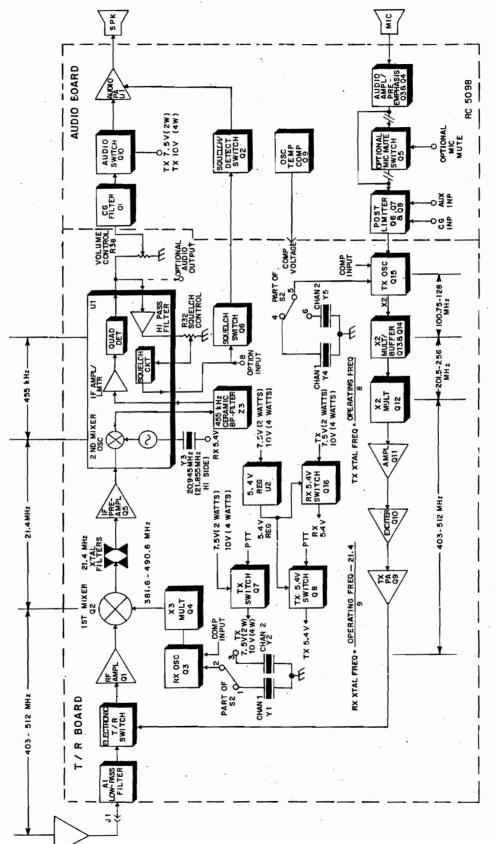


Figure 2 - Block Diagram

L37 in the collector circuit of Q15 is tuned to the second harmonic. L36 provides additional filtering before multiplier/buffer stages Q13 and Q14. Drive to the multiplier/buffer stages can be monitored at J10 (TP4).

MULTIPLIERS

The output of Q13 is tuned to the fourth harmonic by L34 and L35, and applied to the base of multiplier Q12.

The output of multiplier Q12 is tuned to the eighth harmonic by C78 and C81. The emitter voltage of Q12 can be monitored at J9 (TP5).

AMPLIFIERS AND PA

Following Q12 is Class B amplifier Q11. Emitter voltage can be monitored at J8 (TP6). The output of Q11 is tuned by C70 to provide maximum drive to Q10. The output of Q10 is applied to the base of PA transistor Q9. C63 is tuned to provide impedance matching to the PA stage.

A collector feed network consisting of L19, L20, L24, L25, C57, C61, C66, C68, R44 and R47 acts as a stablizing and decoupling network for Q9 and Q10.

Power adjust control C56 is used to set the output power at two watts. The PA output is applied to the antenna switch.

ANTENNA SWITCH

The solid state antenna switch consists of A1-D1, C1, C2, L1 and D1 on the TR board. The circuit acts as a 1/4-wave line simulator.

Keying the transmitter applies approximately 1.6 volts to the anode of A1-D1, forward biasing the diode. When A1-D1 is forward biased, the 1/4-wave line appears as an open circuit to the RF output of the transmitter. This allows the transmitter output to be coupled through the low-pass filter to the antenna. L17, C102 and R43 provide bias and decoupling for the antenna switch.

The antenna switch acts as a 50-ohm line in the receiver mode (A1-D1 not forward biased).

RECEIVER

The receiver is a dual conversion, superheterodyne FM receiver designed for one or two-frequency operation in the 403-512 MHz frequency range. A regulated 5.4 volts is used for all receiver stages

except for the audio PA IC, receiver RF amplifier and mixer which operate from the 7.5 volt battery.

The receiver has intermediate frequencies of 21.4 MHz and 455 kHz. Adjacent channel selectivity is obtained by using three band-pass filters: (2) 21.4 MHz two-pole crystal filters and a 455 kHz ceramic filter.

All of the receiver circuitry except the audio PA and oscillator compensator is mounted on the transmitter/receiver (TR) board. The receiver consists of:

- Receiver Front End
- 21.4 MHz 1st IF circuitry
- 1st and 2nd Oscillators
- 455 kHz 2nd IF circuitry with FM Detector
- Audio PA Circuitry
- Squelch Circuitry

RECEIVER FRONT END

An RF signal from the antenna is coupled through the low-pass filter, antenna switch, and image filter to the emitter of RF amplifier Q1. The image filter consists of C3, C4, C5, C108 and L2.

The output of Q1 is coupled through two tuned circuits that provide most of the front end selectivity. The tuned circuits are L3, R4, C8 and C9, L4 and L5.

OSCILLATOR AND MULTIPLIER

Q3, Y1, D2 and associated circuitry make up a Colpitts oscillator. The frequency is controlled by a third mode crystal operated at one ninth of the required injection frequency. Voltage-variable capacitor D2, L48 and Y1 are connected in series to provide compensation capability. The compensation voltage used to control the transmitter oscillators is applied to D2 to maintain stability. L48 is adjustable to set the oscillator frequency. R8 is in parallel with Y1 to insure operation on the third overtone of the crystal.

The oscillator output is coupled through two tuned circuits (L12-C25 and L13) to the base of tripler Q4. C25 and L13 are tuned to the third harmonic of the oscillator frequency. The output of tripler Q4 is coupled to the gate of first mixer Q2 through two tuned circuits (L14 and L15). L14 and L15 are tuned to

the operating frequency minus 21.4 MHz which is the ninth multiple of the crystal frequency.

The DC level of the oscillator can be monitored at J6 (TP1). The meter reading at this point is typically 5.2 volts. The DC level of tripler Q4 can be measured at J7 (TP2). This meter reading is typically 5.2 volts.

1ST MIXER AND IF FILTER

The 1st mixer uses a FET (Q2) as the active device. The FET mixer provides a high input impedance, high power gain and an output relatively free of intermodulation products).

In the mixer RF from the front end filter is applied to the gate of the mixer. Injection voltage from the multiplier stages is also applied to the gate of the mixer. The 21.4 MHz mixer 1st IF output signal is coupled from the drain of Q2 to crystal filters Z1 and Z2. Tuneable capacitor C12 is used to match the mixer output to the input of Z1.

The highly-selective crystal filter provides the first portion of the receiver IF selectivity. The output of the filter is coupled through R20 to the 1st IF amplifier.

Supply voltage for the RF amplifier and 1st mixer can be metered at J5 (TP3). The meter reading is typically 7.4 volts.

1ST AND 2ND IF AND DETECTOR STAGES

The 21.4 MHz IF output of the crystal filters is applied to the base of IF amplifier Q5. The amplifier provides approximately 12 dB of IF gain. The output of Q5 is coupled through C35 to the input of the 2nd Mixer IC.

U1A and associated circuitry consists of the 2nd oscillator and mixer. The crystal for the oscillator is Y3. The oscillator operates at 20.945 MHz for low side injection of the 2nd IF (standard), or 21.855 MHz for high side injection for those radios determined to be operating on a tweet frequency. This frequency is mixed with the 21.4 MHz input to provide the 455 kHz 2nd IF frequency.

The output of U1A is coupled through ceramic filter Z3 which provides the 455 kHz selectivity. The filter output is applied to U1B.

U1B and associated circuitry consists of an IF amplifier, 455 kHz limiter and a quadrature type FM detector. L10 is the quadrature detector coil. Volume control R38 is used to set the audio

output level to the audio amplifier. R37 and C48 provide a low pass filter to remove 455 kHz from the audio.

AUDIO AND SQUELCH CIRCUITS

Audio

Audio from the VOLUME arm is coupled through a twin-T Channel Guard notch filter that consists of Q1 and associated circuitry. The filter attenuates any audio frequency below 211 Hz.

The audio output from the filter is coupled through receiver muting switch Q10 to audio amplifier U1. Q10 is turned on in the receive mode to pass the audio. The 500 milliwatt audio output of U1 is coupled through C10 to the speaker and earphone jack.

A 6 dB/octave de-emphasis is provided by C12, C6 and R10 in the audio feedback path. R7 and C5 provide additional de-emphasis at higher frequencies.

Squelch

The squelch circuit operates on the noise components contained in the FM detector output. The output of U1B is applied to a high-pass filter consisting of U1C, and associated circuitry. The output of U1C is noise in a band around 8 kHz.

With no RF signal present, the noise is rectified by D4 and a negative voltage is applied to the input of U1D, keeping it turned off and the receiver muted.

Pressing the PTT switch also forward biases clamping diode D5, keeping U1D input bias at the correct standby voltage in the transmit mode.

RECEIVER SWITCH

Releasing the PTT switch turns off the transmitter switches and turns on receiver switch Q16. This applies 5.4 volts to the receiver oscillators, IF amplifier, audio and squelch stages.

When an RF signal is received (receiver unsquelches), no noise is rectified by D4 and the input voltage at pin 12 of U1D rises to approximately +1 volt. This positive voltage turns on U1D, causing the output at U1D-14 to go positive, turning on buffer Q6. When turned on, the collector voltage of Q6 goes low, turning on PNP audio board squelch switch Q2. Turning on Q2 applies 7.5 volts to audio amplifier U1. This turns on U1 so that audio is heard at the speaker.

VOLTAGE REGULATOR AND TR SWITCHES

Turning on-off switch to the "on" position applies 7.5 volts to voltage regulator hybrid, U2. The hybrid provides a continuous, regulated 5.4-Volt output at U2-2.

TRANSMITTER SWITCHES

Pressing the PTT switch turns on Q7 and Q8. When Q7 is turned on, 7.5 volts from the battery is applied to the transmitter multipliers and 1st amplifier stages. The 7.5 volts is also applied to the gate of receiver muting FET Q10. The positive voltage on the gate turns Q10 off and mutes the receiver in the transmit mode. The switched 7.5 volts is also applied to the base of RX 5.4 volt switch Q16, turning the switch off in the transmit mode.

DISASSEMBLY

To remove the front cover for servicing, first remove the battery. Then remove the two screws at A and lift off the front cover (See Figure 3).

To gain access to the back of the TR board, remove the two screws at A and the screw at B and remove the front and back covers.



Figure 3 - Disassembly



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— CAUTION ——

Due to the excellent "drive" capability of the miniature TORX®-head screws, it is relatively easy to overtorque and damage the screws. The torque required for the screws is as follows:

- 1. 4 inch-pounds for the three M2.5 screws in the back cover.
- 2. 2 1/4 inch-pounds for the three M2 screws holding the accessory area cover plate (under the battery).

DO NOT OVERTORQUE!

If the radio is equipped with an option board, in addition to the above steps, the three screws holding the option cover must be removed.

- NOTE -

The option board must be slightly raised to clear the option cover mounting boss before removing the back cover.

- CAUTION -

Do not bend the thin option board material any more than necessary.

REPLACING CHIP COMPONENTS

Replacement of chip capacitors should always be done with a temperature-controlled soldering iron, using a controlled temperature of 700°F (371°C). However, do NOT touch black metal flim of the resistors or the ceramic body of capacitors with the soldering iron.

NOT

The metalized end terminations of the parts may be touched with the soldering iron without causing damage.

REMOVING CHIP COMPONENTS

- 1. Grip the component with tweezers or needle nose pliers.
- Alternately heat each end of the chip in rapid succession until solder flows, and then remove and discard the chip.
- 3. Remove excess solder with a vacuum solder extractor or Solder-wick®.
- 4. Carefully remove the epoxy adhesive and excess flux to prevent damage to the printed board.

REPLACING CHIP COMPONENTS

- Using as little solder as possible, "tin" one end of the component and one of the pads on the printed wiring board.
- 2. Place the "tinned" end of the component on the "tinned" pad on the board and simultaneously touch the component and the pad with a well "tinned" soldering iron while pressing the component down on the board.
- 3. Place the "tinned" soldering iron on the other end of the component and the pad simultaneously. Apply solder to the top of the end of the component until the solder starts to flow. Use as little solder as possible while getting a good joint.
- After the component has cooled, remove all flux from the component and printed wiring board area with alcohol.

HOLE CHART

HOLE	DESCRIPTION				
1	PTT SWITCH GND				
2	OPT. GND				
3	OPT. SW. GND				
4	OPT. 10V[+7.5V]*				
5	PTT FROM OPT.				
6	OPT. +5.4V REG.				
7	DISCRIMINATOR OUTPUT				
8	OPT. MUTE				
9	PTT OUTPUT TO OPTIONS				
10	PTT SWITCH (HOT)				
11	CG TONE INPUT TO XMTR				
12	FROM OPT. TO OPT. SW. CONN.				
13	FROM OPT. SW. TO OPT. CONN.				
14	PTT OUTPUT FROM OPTIONS				
15	SQUELCH FROM OPTIONS				
16	TX 10V[+7.5V]*				
0					
18 .	JUMPER WIRE				
19					
20	GND. FOR RF CHOKE				
21	OPTION SW GND FOR MIN LO VOL OPTION				

TEST POINT CHART

TP	FUNCTION	TYPICAL V
1	RX Injection Tuning	5.2
2	Rx Injection Tuning	5.2
3	RX Injection Tuning	9.90[7.40]
4	TX Drive Tuning	0.4
5	TX Drive Tuning	0.6
6	TX Drive Tuning	0.8
7	Battery Input	10V[7.5V]
8	Ground	0

^{* [] =} Voltages in brackets are for 2-Watt Transmitters

LBI-31496

4EX12A12 - Personal Radio Test Set (Does not include any interconnect cables)

SERVICE TOOLS

19B234242G1 - Internal J4 Interconnect
Cable (May be used with any
MPI radio)

19B234242G2 - External Audio Jacks Interconnect Cable (Only used on units with remote mic capability)

Option 4120 - (Replaced TS 10 Service

Tool Kit)
ST 2513 - Coil and Trim Pot
Alignment Tool

ST 2521 - Oscillator Coil Align-

ment Tool ST 2519 - Johanson Capacitor

Alignment Tool
(0.029" tip)

ST 2520 - Johanson Capacitor
Alignment Tool

(0.025" tip)

19A702672P1 - Battery Test Lead
(Black)

19A702672P2 - Battery Test Lead (Red)

(Red)
19B800747P3 - Audio Board Jumper
Cable. Tin Contacts. (2 Required)

19B801406P57 - Audio Board Jumper Cable. Gold Con-

tacts. (2 Cables Required) 19A144745G1 - Receiver Audio Test

Cable
19B800968G1 - RF Probe Assembly

19D900773G1 - 7.5 Volt Dummy Battery Pack

19D900773G2 - 10 Volt Dummy Battery Pack

Mechanical Tools:

ST 2307 - Spanner wrench for audio

jacks

ST 2311 - Spanner wrench for volume & squelch controls

ST 0720 - Hex driver & assortment

of 9 TORX bits

SYMPTOM	PROCEDURE
No 10V[7.5V] Supply	Check power connections and continuity of supply leads, and check fuse. If fuse is blown, check radio for shorts.
Low 10V[7.5V] Supply	Check for low or uncharged battery possibly with bad cell.
No 5.4V Regulated Supply	Check the 10V[7.5V] supply at pin 3 of regulator Q2. If a large standby current (i.e., >100 mA) is seen, check for a short to ground on the 5.4V output line.
No Rx	Check the 5.4V regulated supply. Then check 5.4V switching transistor Q15.
No Audio Output	Check audio board squelching transistor, Q2. If the audio amplifier U1 is properly biased on, inject a 50 mV RMS, 1 kHz signal into the preceding stages until the faulty stage is isolated as follows. This signal must be capacitively coupled from the audio generator using a 1 uF electrolytic capacitor to avoid shifting bias voltages. Sequentially inject signal into the following points on the audio board: Pin 3 of U1, emitter of Q1, base of Q1, and P2-5 (volume control dependent). If the problem is not found on the audio board, check for recovered audio on the main board with an oscilloscope. Recovered audio should be seen at Pin 9 of U1, at Hole 7, and at Pin 3 of R40 (as well as the wiper depending upon position).
Low Audio	Measure supply voltage at Pin 6 of audio board IC (U1) and gate voltage of Q10. Verify that at least 150 mV (424 peak-to-peak) is present at Hole 7 when a strong RF signal is applied to the radio with standard test modulation. Check quad coil (L16) setting.
Distorted Audio Output	Apply a strong RF signal with standard test modulation and measure audio distortion into an 8 ohm dummy load (e.g., test adaptor box). Distortion should be less than 5% at 2 volts output at 1 kHz. If there is low electrical distortion and acoustical distortion is still present, listen with test box or swap front covers with another radio to test speaker.
No or Incorrect Detector Output	Verify bias to Pins 4 and 8 of the main board IC, U1. Using a 50 ohm probe, inject a strong 10.7 MHz modulated signal into Pin 16 of U1. Recovered audio should be seen at Pin 9 and the level should vary with the setting of quad coil, L16. If none is seen, check the second oscillator for activity. At least 80 mV of RF should be seen on Pin 1 to ground.
No 2nd Oscillator Activity	Substitute a known good crystal for Y3. Check voltages on U1 pins 1 and 2.
Radio Permanently Squelched	Verify that main board IC, U1, is properly biased at Pins 4 and 8 and that quad coil L16 is correctly adjusted. The voltage at the Schmidt trigger input (U1 Pin 12) should rise and fall with the setting of R34. The output at pin 14 should switch bias on and off to the base of Q6 as the input threshold is crossed. The collector of Q6 should saturate and unsquelch the radio once the input (Pin 12) is above the threshold, approx. 0.8V.
Radio Won't Squelch	Verify that main board IC, U1, is properly biased at Pins 4 and 8 and that quad coil L16 is correctly adjusted. An oscilloscope should see high frequency (approx. 8 kHz) noise at the noise filter output, U1 pin 11. This noise should be seen at the wiper of R34 (dependent upon position) and should be negatively rectified by D4. The remainder of the squelch circuit is described under the "Radio Permanently Squelched" section.

TROUBLESHOOTING PROCEDURE

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Issue 1

SYMPTOM	PROCEDURE
Poor or No Sensitivity	Verify that proper injection power is present and at the correct frequency, (f -10.7). This can be done by 50 ohm probe across L40. The power seen should be approximately 0 dBm. If OK, then use the 50 ohm probe with a signal generator to inject signal into various portions of the radio to isolate the bad section. Set the generator with standard modulation to the level and frequency indicated on the large service schematic and probe those points starting with the IC (U1) and moving forward to the antenna jack. In some cases parts must be adjusted for best sensitivity while probing. This is indicated on the schematic. Once the faulty stage is isolated, measure bias voltages.
No or Low Injection Power	Verify that tuning procedure has been done or tried. The oscillator string can be trouble shot by using a 50 ohm probe connected to a power meter capable of measuring power as low as -20 dBm. Probe the available power points to ground indicated on the large service schematic. The power seen should be approximately that shown on the schematic. Any adjustment needed during probing is indicated on the schematic. Start probing with the oscillator and proceed towards the mixer. Bias voltages are also shown on the schematic for both a running and non-running oscillator. To kill a running oscillator, place a .01 uF ceramic capacitor with short leads from the base to collector of the oscillator transistor Q3.
Receive Frequency Won't Adjust Properly	Check compensator voltage at P3-2 and at varicap (D2 or D9). Check anode voltage of varicap.
No Transmit	Check the switching transistor Q14.
Radio Won't Go Into Transmit Mode	Verify that Hole 9 is going to ground when the PTT switch is pushed. If Channel Guard is present, first short Hole 9 and then Hole 5 to ground. Both operations should cause the radio to go into transmit mode unless a problem exists with the Channel Guard circuitry.
Low or No Transmit Power	Check battery voltage when in transmit. Low or uncharged battery or shorted cell will be <7 volts If the total transmit current is >500 mA, check the low pass filter and T/R switch. 1.6 VDC at C91 indicates that the radio is in the transmit mode. If the total transmit current is <100 mA, measure the base bias of Q13. Check for proper test point readings at TP4, TP5, TP6.
High TP6	0.2 - 0.4 VDC indicates proper drive into Q11. 0.6 VDC indicates no drive. Check the bias voltages.
Low TP5	0.7 - 0.9 VDC indicates proper drive into Q12. 0.5 VDC indicates no drive. Check the bias voltages.
High TP4	0.3 - 0.5 VDC indicates proper drive from the oscillator. With no oscillator activity TP4 will be 0.7 VDC.
Transmit Frequency Will Not Adjust Properly	Check the compensator voltage at P3-2. Check the anode voltage of the varicaps (D6 or D7).
No Transmitter Deviation	Disconnect the front cover and connect the test box. Apply 600 mV to TX audio. Check the DC and Audio Voltages on the Audio Board as indicated on the service schematic during transmit. If values are as indicated, substitute another front cover to test the microphone.

TRANSMITTER ALIGNMENT

EQUIPMENT REQUIRED

- 1. Power Supply (10 Volts, 2 Ampere).
- 2. 50 ohm Wattmeter with 50 ohm load
- 3. Audio Oscillator
- 4. Deviation Monitor
- 5. Frequency Counter
- 6. Digital Voltmeter
- 7. Tune-up Kit Option 4120 (contains coil tuning tools, capacitor tuning tools, dummy battery, audio board jumper cables, and a 50 ohm probe).
- 8. Test adaptor 4EX12A12 and cable 19B234242G1 (Option 2847).

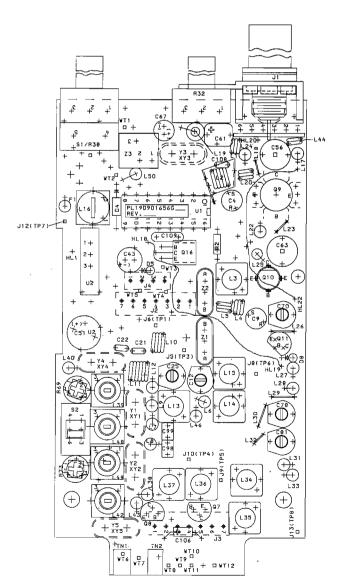
PRELIMINARY STEPS AND ADJUSTMENTS

1. In addition to the antenna mounting bracket screw, the radio must be held tight against the back cover at the lower right corner near the negative battery terminal (e.g. use a 4-40 screw and nut).

- 2. Unplug the audio board and front cover from the main board.
- 3. Insert the dummy battery into the battery pack area and apply nominal battery voltage (7.5 or 10 Volts as required) to the RED terminal (BLACK terminal is ground) on dummy battery pack.
- 4. Pre-set the tuning slugs in L39 (and L42 in two-frequency radios) to the center of their tuning range. Next, set the slugs in coils L34 through L37 flush with the top of the coil form. Then set the arrows on the rotors of C70, C78 and C81 pointing to the rounded end of the capacitor.
- 5. All adjustments are made with the transmitter keyed and Channel Guard enabled, if present.

— note —

In two-frequency radios, switch to the highest frequency.



ALIGNMENT PROCEDURE

LBI-31496

ALIGNMI	ENT PROCEDURE		
STEP	METERING POINT	TUNING CONTROL	PROCEDURE
1.	TP4	L37 and L36	Adjust L37 and L36 in that order for a dip in meter reading. Repeat if necessary.
2.	TP5	L34 and L35	Adjust L34 and L35 in that order for a peak in meter reading. Repeat if necessary.
3.	TP6	C81 and C78	Adjust C81 and C78 in that order for a peak meter reading. Repeat if necessary.
4.	Wattmeter	C70, C63 C56	Adjust C70, C63 and C56 in that order for maximum power output.
5.	Wattmeter	C56	Turn C56 in the direction that causes both the power and current to decrease, and ad- just C56 for an output of 2.2 Watts or 4.4 watts as applicable.
			NOTE If the radio draws more than rated current, spread the turns on L44 and re-adjust C56 for maximum power output. Then repeat Step 5.
		FRI	EQUENCY ADJUSTMENT
6.	Frequency Counter	L39 and L42	Plug the audio board onto the main board. In single frequency radios, adjust L39 for the proper frequency. In two frequency radios, switch to Channel 1 and adjust L39 for the proper frequency. Then switch to Channel 2 and adjust L42 for the proper frequency.
		MOM	JLATION ADJUSTMENT
7.	Deviation Monitor	R69 and R73	Connect the test adaptor with cable to J4 and switch to channel 1. Apply 600 millivolts at 1 kHz to the test adaptor and adjust R69 for 4.5 kHz deviation with Channel Guard enabled, if present. In two-frequency radios, switch to channel 2 and adjust R73 for 4.5 kHz deviation with Channel Guard enabled, if present.

ALIGNMENT PROCEDURE

TRANSMITTER

RECEIVER ALIGNMENT

EQUIPMENT REQUIRED

- 1. 10-Volt Power Supply. (0.5 amps)
- Floating terminal (non-grounded) multimeter with at least 3 1/2 digits and a 200 millivolt DC lowest range.
- 3. RF generator.
- 4. Distortion analyzer.
- MPI Tune-up kit Option 4120 containing coil tuning tools, trimmer capacitor tuning tools, dummy battery, audio board jumper cables and a 50 ohm probe.
- 6. Test Adaptor 4EX12A12 and MPI Cable 19B234242G1 (Option 2849 for internal jack, or Option 4990 for jacks on side rail.

PRELIMINARY CHECKS AND ADJUSTMENTS

 In addition to the antenna mounting bracket screw, the radio must be held tight against

- the back cover at the lower right corner near the negative battery terminal or TP8 (e.g. use a 4-40 screw and nut).
- 2. Remove the front cover and unplug the Audio board from the main board. Then connect the audio board to the main board with the jumper cables.
- 3. Insert the dummy battery into the battery pack area and apply nominal supply voltage (7.5 or 10 Volts as required). Volts to the RED terminal (BLACK terminal is ground) on dummy battery.
- 4. Pre-set the tuning slugs in L3, L13, L14, L15, L48 and L49 to the top of the coil form. Then set the arrow on the rotor of C12 and C25 so that it points towards the rounded end of the capacitor.
- 5. Disable Channel Guard, if present.

- NOTE -

In two-frequency radios, all adjustments are made on the lowest frequency except as directed.

ALIGNMENT PROCEDURE

STEP	METERING POINT	TUNING CONTROL	PROCEDURE
1.	Audio Output Jack (J1 on side panel)	L16	Set the Volume Control an audio level of approximately 1 Volt RMS to keep out of limiting. Using the 50 ohm probe, apply a strong modulated 21.4 MHz signal (>-50 dBm) to U1A-16 on T/R board and adjust L16 for maximum audio output. NOTE If a 21.4 MHz generator is not available, adjust L16 for maximum noise.
2.	J2-7 and TP1	L48 (Chan 1) or L49 (Chan 2)	For two frequency radios, select the lowest frequency. While measuring between J2-7 (regulator voltage) and TP1, adjust L48 or L49 for maximum meter reading (approximately 250 millivolts).
3.	Audio Output Jack (J1 on side panel)	C25, C9 and L13	Apply a strong (0 dBm) signal to the antenna jack. Adjust C25, C9 and L13 for best quieting. C25 will have more than two dips, so use only the stronger one. Then adjust C25 and L13 again for best quieting.
4.	Audio Output Jack (J1 on side panel)	L14, L15, C4, L3 and C9	Adjust L14, L15, C4, L3 and C9 in that order for best quieting. NOTE If L15 does not tune properly (multiple dips, no dips, etc.), set the arrow on C12 towards the flat end of the capacitor.

ALIGNMENT PROCEDURE

RECEIVER

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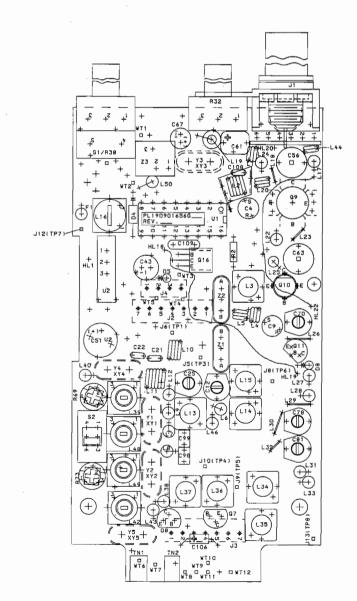
Issue 2

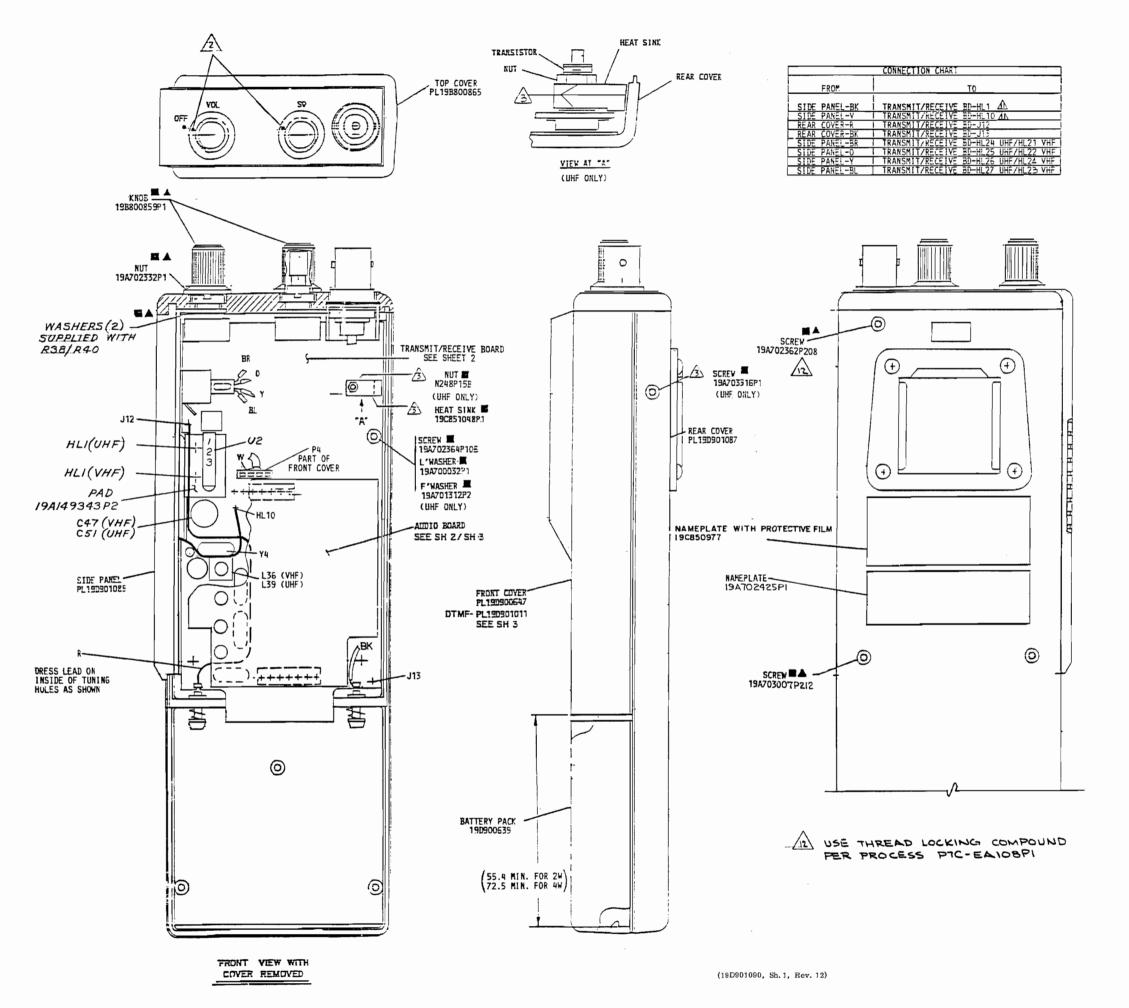
TUNING PROCEDURE STEP METERING CONTROL POINT 5. Distortion L48, L49 Add 1 kHz tone modulation at 5 kHz deviation and C12 to the carrier. Leave the Volume control as Analyzer in Step 1. Alternately adjust lowest frequency warp coil (L48 or L49) and C12 until no improvement in SINAD is seen. This will insure that the match to the crystal filters is properly adjusted, and that the carrier is centered in the pass band (zero beating isn't required). On 2 frequency radios switch to the other channel and adjust the other warp coil (L48 or L49) for best SINAD. On two-frequency radios, switch to the lowest frequency. Set the signal generator Distortion Analyzer to the image frequency (42.8 MHz below the carrier frequency) and increase the RF level to approximately -60 dBm. Then adjust C4

for the amount of image rejection desired by

degrading the quieting on SINAD. Then reset the signal generator to 3 kHz before doing

any standard measurements.





- 1 VHF SEE NOTES A S &
- 2 UHF SEE NOTE 8
- 3 VHF TWO FRED TX & SINGLE FRED RX SEE NOTES 4
- UHF TWO FRED TX & SINGLE FRED RX
 SEE NOTE 6
- 5 DTMF SEE SH. #3
- 6 VHF SINGLE FREQ TX & TWO FREQ RX SEE NOTES
- 7 UHF SINGLE FRED TX 8 TWO FRED RX
 SEE NOTE 7

NOTES:

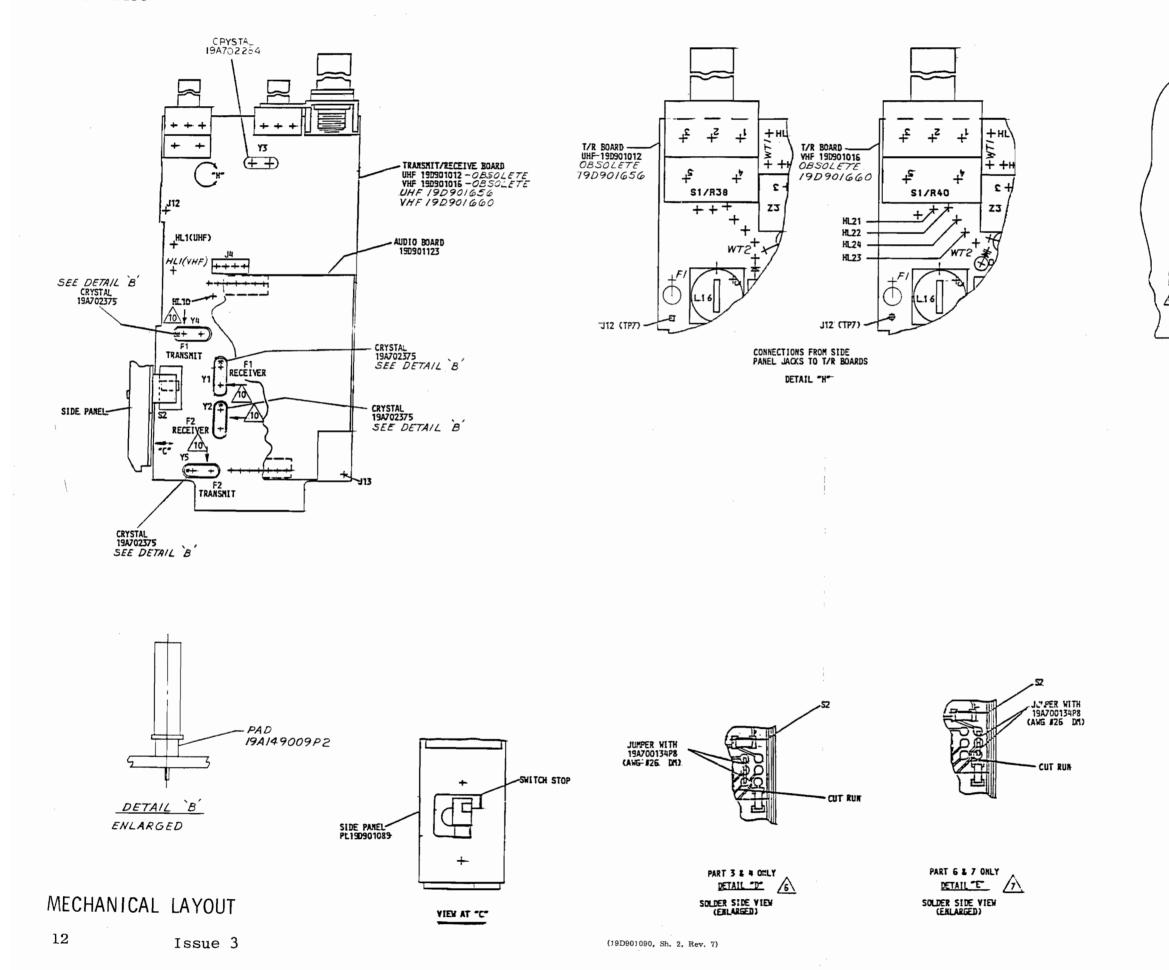
- ITEMS MARKED ARE PART OF HARDWARE KIT PL19A702379G2 (UHF). ITEMS MARKED ▲ ARE PART OF HARDWARE KIT PL19A702379G3 (VHF).
- ROTATE OFF/ON-VOL POT TO EXTREME COUNTER CLOCKWISE (OFF) POSITION.
 ASSEMBLE KNOB WITH INDICATOR MARK ALIGNED WITH MARK ON TOP COVER.
 ROTATE SQUELCH POT TO EXTREME COUNTER CLOCKWISE POSITION. ASSEMBLE KNOB WITH INDICATOR MARK IN APPROXIMATELY SAME POSITION AS THE
- APPLY SILICON GREASE (19A701337P1 P)PER 19A701431 BETWEEN MATING SURFACES OF HEAT SINK, NUT, TRANSISTOR AND REAR COVER. SCREW MUST BE TIGHTENED BEFORE NUT. NUT TIGHTENING TORQUE TO BE .3 N-M
- A. CUT RUN ON SOLDER SIDE OF TX/RX BOARD /9D90/6606/WHEN LOWEST
 TX FREQ. SPECIFIED IS BELOW 142 MHz OR ON TX/RX BOARD /9D90/66062
 WHEN LOWEST TX FREQ. SPECIFIED IS BELOW 162 MHz AS SHOWN IN
 DETAIL "5" (SH. #2).

 B. CUT RUN ON SOLDER SIDE OF TX/RX BOARD /9D90/66062 WHEN HIGHEST
 RX FREQ. SPECIFIED IS BELOW 162 MHz AS SHOWN IN DETAIL "6" (SH. #2)
- A. WHEN NO TX CRYSTALS ARE SPECIFIED ON PRODUCTION TAG DO NOT CUT RUN SHOWN IN DETAIL "6" (Sh. #2) PER NOTE 4.A.

 B. WHEN NO RX CRYSTALS ARE SPECIFIED ON PRODUCTION TAG DO NOT CUT RUN SHOWN IN DETAIL "6" (Sh. #2) PER NOTE 4.B.
- CUT RUN CN SCLDER SIDE OF TX/RX BOARD AND ADD JUMPERS AS SHOWN IN DETAIL "D" (SH. #2).
- CUT RUN ON SOLDER SIDE OF TX/RX BOARD AND ADD JUMPERS AS SHOWN IN DETAIL "E" (SH. #2).
- SWITCH STOP IS TO BE INSTALLED UNLESS 8TH DIGIT OF COMBINATION NUMBER IS C', D' OR CRYSTALS ARE INSTALLED IN CHANNEL 2 TX AND/OR RX.

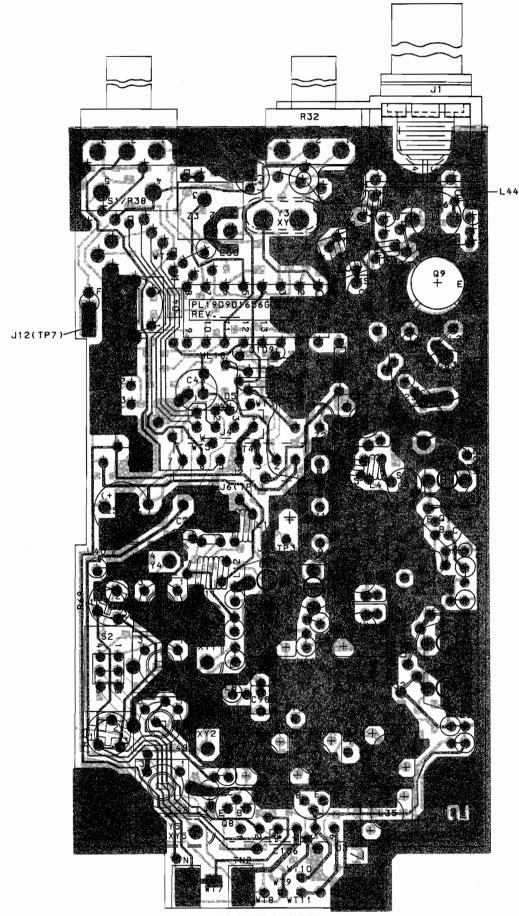
- 9. SOLDER ALL ELECTRICAL CONNECTIONS.
- ORIENT Y1. Y2, Y4 AND Y5 SO THAT DWG. NO. & FREQ. MARKING IS AT SIDE INDICATED. GROUND LEAD MUST BE IN POSITION AS INDICATED BY * (SH. #2)

MECHANICAL LAYOUT



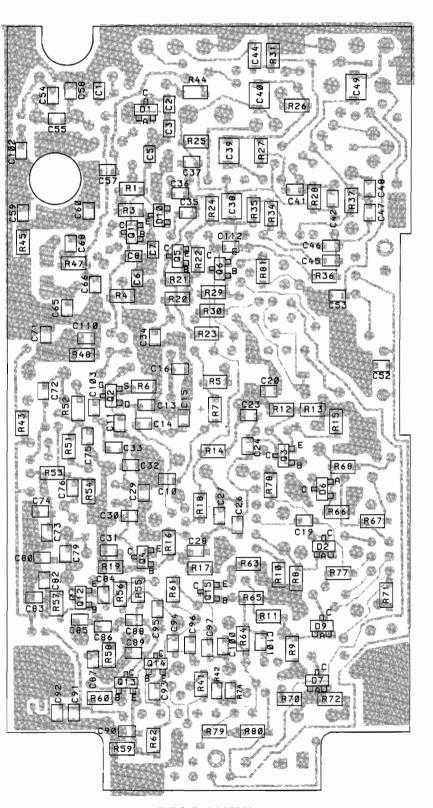
VHF T/R BOARD PL19D901016 - OBSOLETE PL19D901660

DETAIL "G" SOLDER SIDE VIEW (ENLARGED)



FRONT VIEW

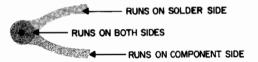
(19D901658, Rev. 5) (19A704667, Sh. 1, Rev. 2)



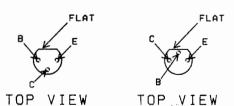


(19D901656, Sh. 1, Rev. 8) (19A704667, Sh. 2, Rev. 2)





LEAD IDENTIFICATION LEAD IDENTIFICATION FOR Q7,Q8 & Q16 FOR Q1!



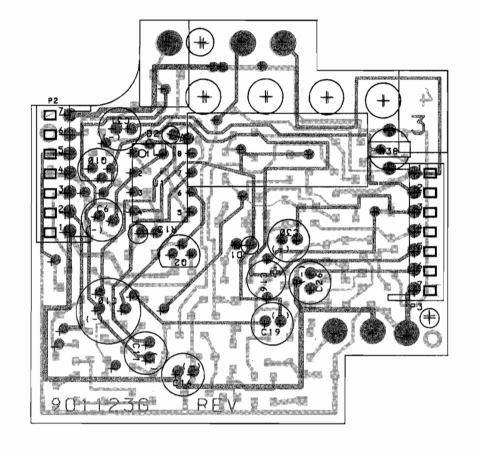
NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

OUTLINE DIAGRAM

TRANSMITTER/RECEIVER BOARD

Issue 3

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| Total | Tota

FRONT SIDE

BACK SIDE

(19D901124, Rev. 5) (19A703568, Sh. 1, Rev. 3) (19A703568, Sh. 2, Rev. 4)

(19D901123, Rev. 7) (19A703568, Sh. 2, Rev. 4) LEAD IDENTIFICATION FOR Q2



IN-LINE TOP VIEW

NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

LEAD IDENTIFICATION FOR Q10



IN-LINE TOP VIEW

NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

LEAD IDENTIFICATION FOR Q1,Q3 THRU Q9



TOP VIEW

RUNS ON SOLDER SIDE

RUNS ON BOTH SIDES

RUNS ON COMPONENT SIDE

OUTLINE DIAGRAM

AUDIO BOARD

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Issue 3

FREQUENCY SENSITIVE COMPONENTS

		REGUENCT SEN			
REF.	61 & 613	G2 & G14	63 & 615	G4 & G16	G5 & G17
NO.	450-470 MHZ	470-494 MHZ	489-512 MHZ	403-425 MHZ	420-450 MHZ
C1#	5.6P	5,6P	5,6P	6.8p	5.6P
C2#	6.8p	6.8=	3.9p	8.2p	6.8P
C3#	2.7P	2.7P	2.7P	3.3p	3.3P
C4	0.5-2.5p	0.5-2.5p	0.5-2.5p	1-5p	1-5P
C5#	2.7p	2.7p	2.7p	3.3p	3.3p
C8#	1.2P	0.9P	0.7P		
				2.2p	1.8p
C19#	100P	100p	100p	68P	150p
C22	68P	68₽	68P	120p	120p
C23#	22P	15p	15P	30p	24P
C24#	3.3p	4.7p	4.7P	4.7P	4.7p
°C27#	15p	12P	13p	22p	18p
C30#	2.7p	1 . 8 P	1.8p	3.3P	2.7p
C32#	3.3p	2.7p	2.7p	4.3p	3.9p
C54#	1 OP	8.2P	8.2P	12P	12p
C55#	3.9p	NONE	NONE	8.2p	5.6P
C59#	15e	10r	8.2P	15p	15p
C59#	39p	36p	33 _P	47P	43P
C60#	39p	36P	33 _P	47P	43P
C65#	15p	12P	6.8p	24P	22P
C71#	1 OP	10P	8.25	15p	1 OP
C85#	39p	39P	39 _P	43P	39p
C86#	22P	22P	22p	33P	24P
C87#	39p	33 _P	33 _P	51 P	43P
C89#	10p	10P	8.2P	12p	12p
C93#	39p	39p	39P	43P	39p
C94#	1 8p	18=	18p	27 _P	22 _P
C95#	47p	47 P	47 P	56P	47P
C96#	2.7P	2.7P	2,2P	3.3P	2.7p
C97#	30p	27P	27P	39P	36P
C108	6.8P	4.7p	4.7P	6,8P	6.8p
C110#	10p	10P	NONE		
	2 1/2 TURNS	2 1/2 TURNS	2 1/2 TURNS	15p 2 1/2 TURNS	10P
L1	2.0mm ID				2 1/2 TURNS
		1.79mm ID	1.78mm ID	2.2mm ID	2.2mm ID
L4 & L5	2 1/2 TURNS		2 1/2 TURNS		2 1/2 TURNS
	2.0mm ID_	2.Omm ID	1.78mm ID	2.Omm ID	2.Omm ID
L7 & L8	14	1 u	1 u	1.2u	1.2u
L9	680n	680n	560n	1 u	920n
L11	5 1/2 TURNS			5 1/2 TURNS	5 1/2 TURNS
	3.04mm ID	3.04mm ID	3.04mm ID	3.04mm ID	3.04mm ID
L12	150n	120n	120n	150n	150n
L38	270n	270n	220n	470n	390n
L44		1 1/2 TURNS	1 1/2 TURNS		
	2.0mm ID	1.52mm ID	1.52mm ID	2.Omm ID	2.0mm ID
L 45	3 3/4 TURNS		3 3/4 TURNS		3 3/4 TURNS
275	2.54mm ID	2.54mm ID	2.03mm ID	2.54mm ID	2.54mm ID
R15#	560	560	560	390	390
R77#	22k	22k	22k	18k	18k
R78#	68k	68k	68k	82k	82k
R79#	47k	47k	47k	47k	47k
R80#	82k	82k	82k	82k	82k
		(,	461,		<u> </u>

VOLTAGE READINGS:

VOLTAGE READINGS ARE TYPICAL VALUES MEASURED WITH A HIGH IMPEDANCE (****) 10M \(\text{M} \) NULTI-METER FROM THE INDICATED POINT TO GROUND. CONDITIONS FOR READINGS ARE INDICATED BY THE FOLLOWING KEY:

- R INDICATES VOLTAGES ARE TO BE MEASURED DURING RECEIVE MODE
 T INDICATES MEASUREMENT DURING TRANSHIT C INDICATES CONTINUOUS VOLTAGE ALWAYS PRESENT WHEN RADIO IS ON

VOLTAGE READINGS ARE FOR 4 WATT MPI UNITS UNLESS ENCLOSED IN BRACKETS WHICH INDICATES VOLTAGES MEASURED ON 2 WATT MPI UNITS. (EXAMPLE, [+7.5V])

NOTES

A PART OF PWB.

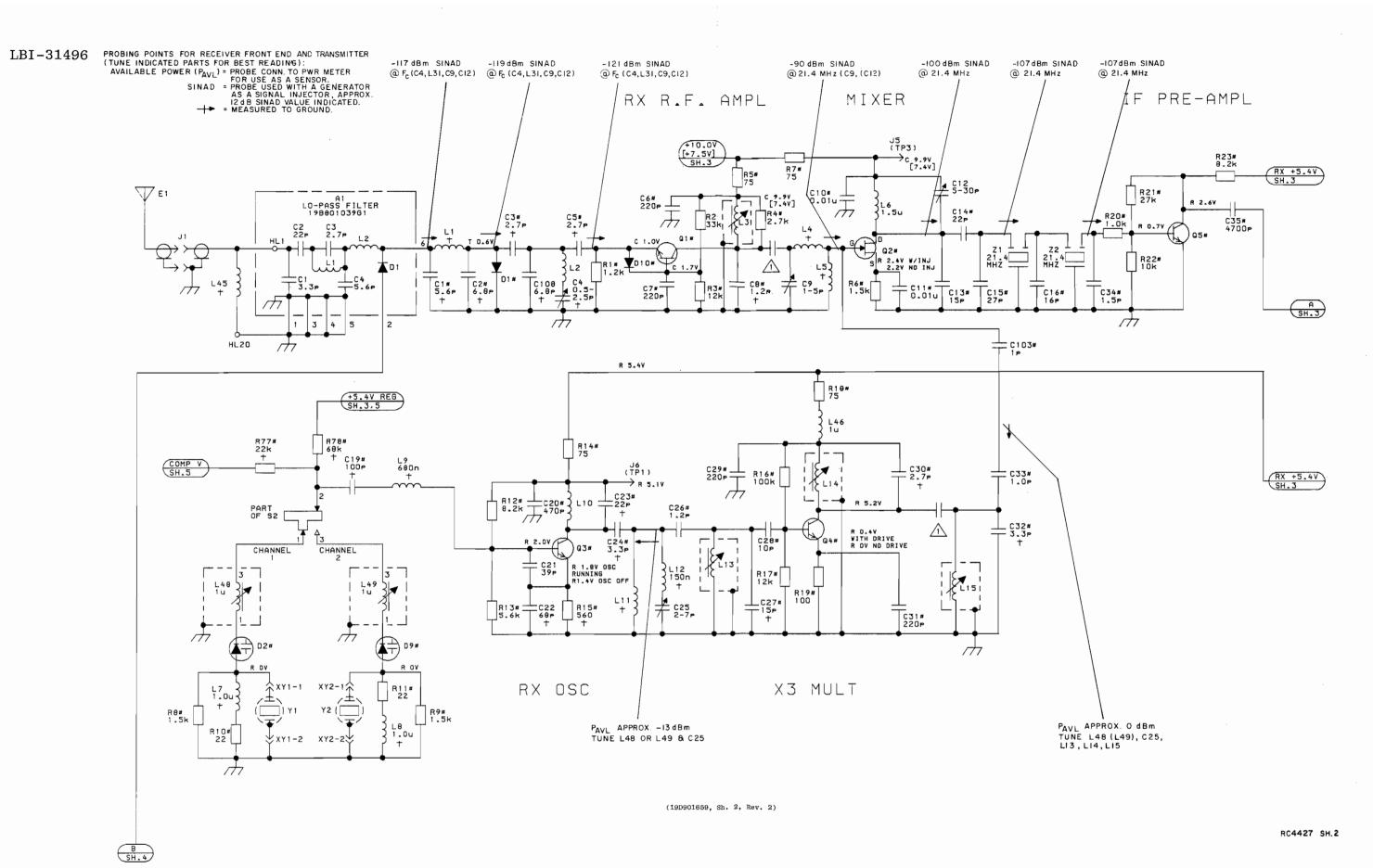
- 3. * IDENTIFIES "CHIP" COMPONENTS (EXAMPLE C57*)
 WHICH ARE LOCATED ON SOLDER SIDE OF PWB.
- 4. † FREQUENCY SENSITIVE COMPONENTS, SEE COMPONENT IDENTIFICATION CHART OR PARTS LIST. G! PART VALUE SHOWN.
- 5. ALL CHIP RESISTORS ARE 1/8 WATT.
 ALL OTHER RESISTORS ARE 1/8 WATT UNLESS OTHERWISE SPECIFIED.
 RESISTOR VALUES IN Ω UNLESS FOLLOWED BY MULTIPLIER k OR M.
 CAPACITOR VALUES IN F UNLESS FOLLOWED BY MULTIPLIER u,n OR p.
 INDUCTANCE VALUES IN H UNLESS FOLLOWED BY MULTIPLIER m,u OR n.

CUT THIS RUN FOR CG/CCT OPTION.

DESCRIPTION	MODEL NO.	REV LTR
UHF 2W/4W MAIN BD 450-470 MHZ	PL19D901656G1	ם
UHF 2W/4W MAIN BD 470-494 MHZ	PL19D901656G2	Ö
UHF 2W/4W MAIN BD 489-512 MHZ	PL19D901656G3	Ε
UHF 2W/4W MAIN BD 403-425 MHZ	PL19D901656G4	0
UHF 2W/4W MAIN BD 420-450 MHZ	PL19D901656G5	C
UHF 2W/4W MAIN BD 450-470 MHZ	PL19D901656G13	В
UHF 2W/4W MAIN BD 470-494 MHZ	PL19D901656G14	В
UHF 2W/4W MAIN BD 489-512 MHZ	PL19D901656G15	С
UHF 2W/4W MAIN BD 403-425 MHZ	PL19D901656G16	В
UHF 2W/4W MAIN BD 420-450 MHZ	PL19D901656G17	A E
AUDIO BOARD (STANDARD)	PL19090112361	
AUDIO BOARD (W/DTMF PARTS)	PL19D9O1123G2	Ε
AUDIO BOARD (STANDARD) (GOLD)	PL19D901123G7	Α
AUDIO BOARD (W/DTMF PARTS) (GOLD)	PL19D901123G8	A
BATTERY (7.5V)	PL19D900639G2	
BATTERY (10V)	PL19D900639G3	
REAR COVER (2 WATT)	PL19D901087G4	
REAR COVER (4 WATT)	PL19D901087G2	
SIDE PANEL	PL19D90108961	
FRONT COVER (STANDARD)	PL19D900647G1	
FRONT COVER (LICENSEE)	PL19D900647G2	
FRONT COVER (STANDARD W/O METAL)	PL19D900647G4	
FRONT COVER (STANDARD/DTMF)	PL19D9D1011G1	
FRONT COVER (LICENSEE/DTMF·)	PL19D90101162	

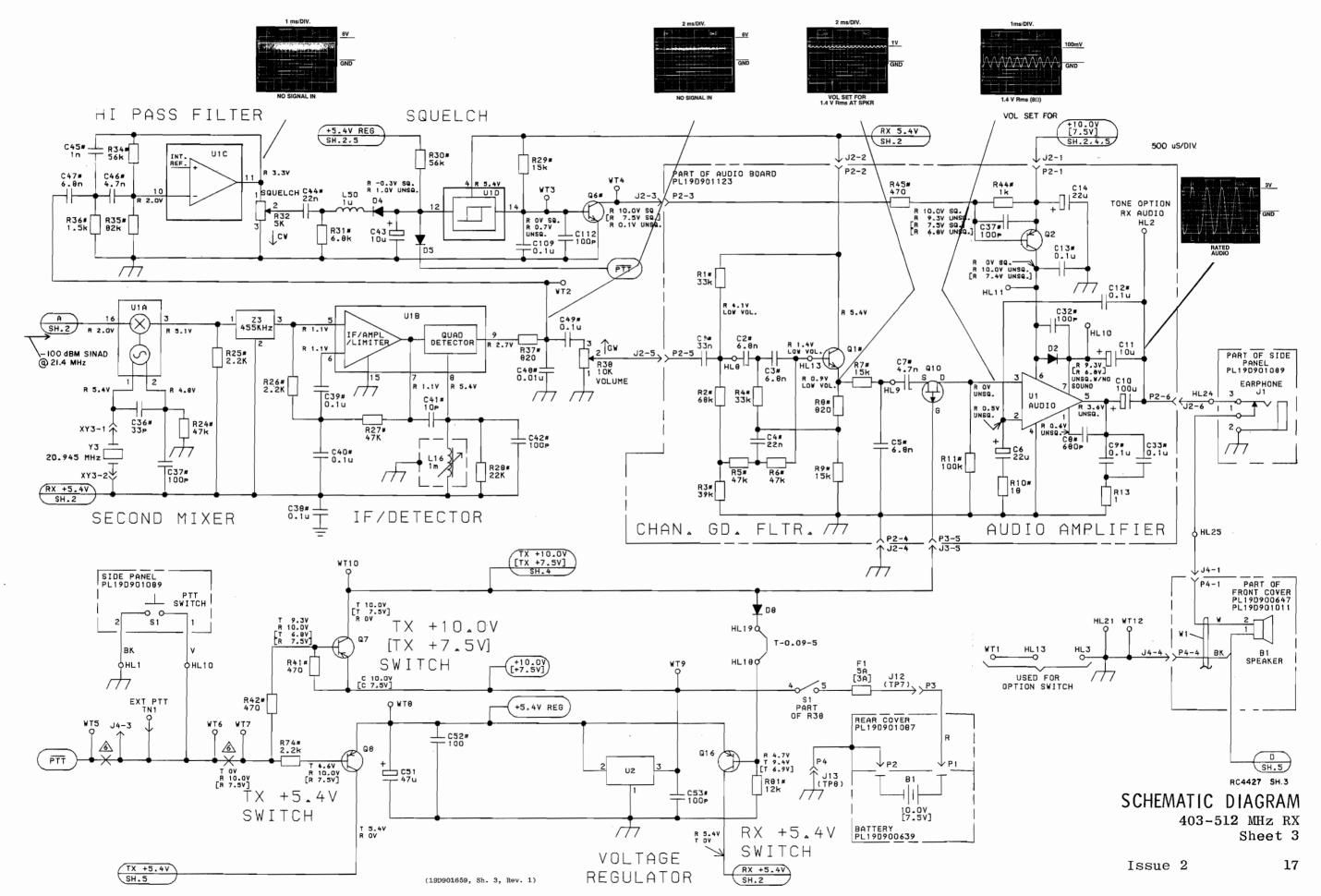
(19D901659, Sh. 1, Rev. 9)

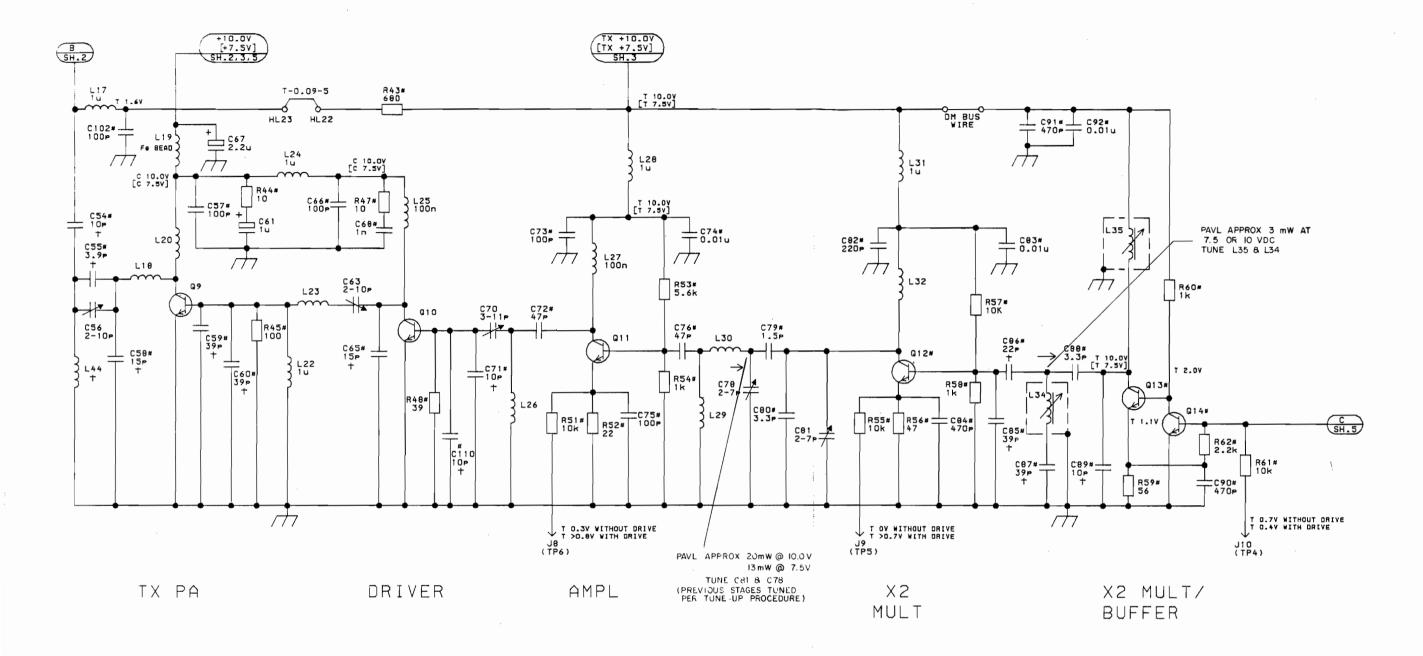
SCHEMATIC DIAGRAM



SCHEMATIC DIAGRAM

403-512 MHz RX Sheet 2 16 Issue 2





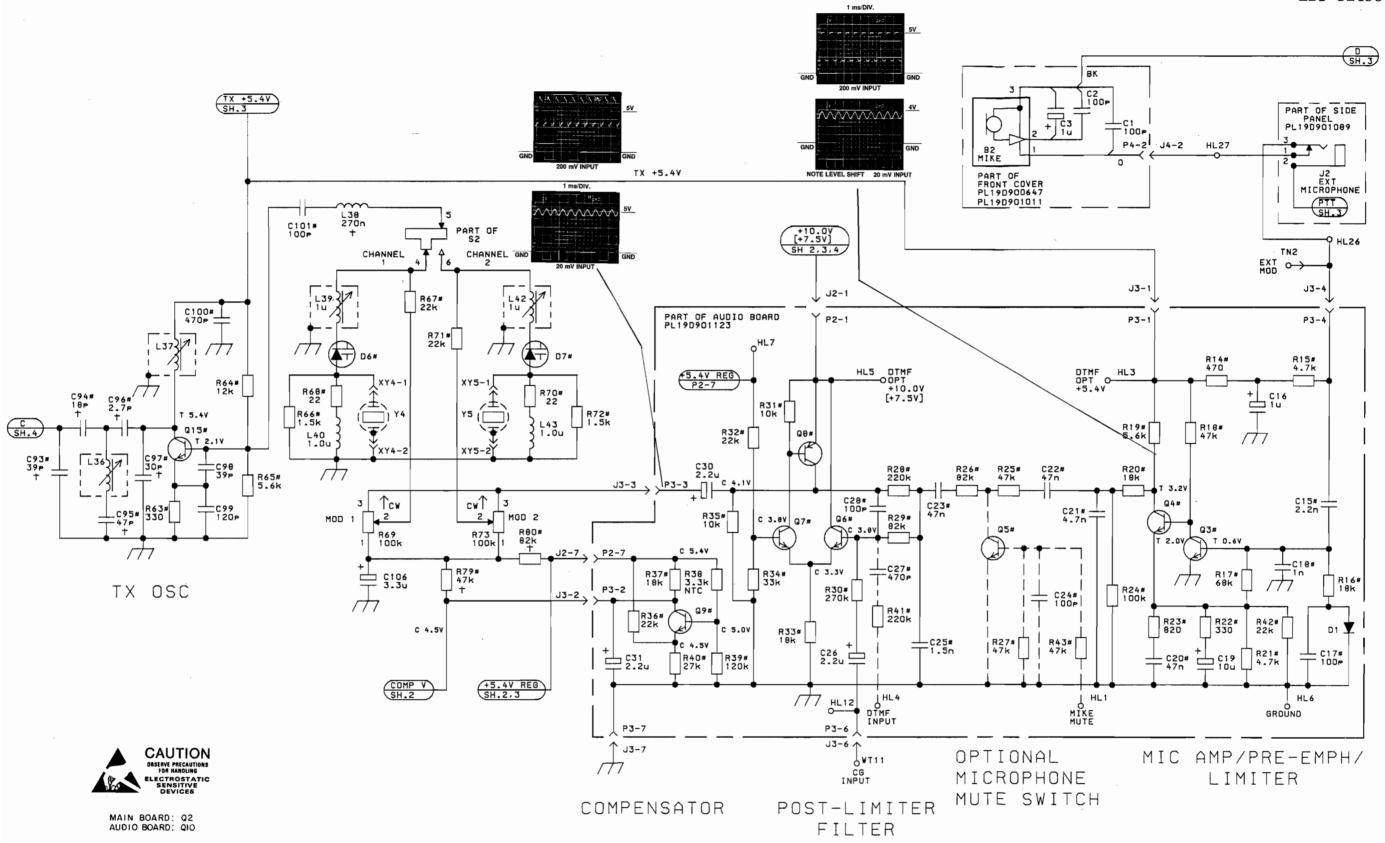
(19D901659, Sh. 4, Rev. 2)

403-512 MHz TX Sheet 4

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Issue 2

RC4427 SH.4



RC 4427 SH. 5

SCHEMATIC DIAGRAM

403-512 MHz TX Sheet 5 Issue 2 19

PARTS LIST

TRANSMIT/RECEIVE BOARD 19D901656G1-G5, G13-G17

ISSUE 3

TO ASSUEE BOARDS WITH GOLD CONTACTS ARE NOT INTERNIZED WITH BOARDS HAVING TIN CONTACTS. REPLACE ONLY WITH SAME GRAP NUMBER AS ORIGINAL. C1		GE PART NO.	DESCRIPTION
TO ASSUEE BOARDS WITH GOLD CONTACTS ARE NOT INTERNIZED WITH BOARDS HAVING TIN CONTACTS. REPLACE ONLY WITH SAME GRAP NUMBER AS ORIGINAL. A1			19D901656G2 470-494 MHz 19D901656G3 489-512 MHz 19D901656G4 403-425 MHz 19D901656G5 420-450 MHz 19D901656G13 450-470 MHz GOLD CONTACTS 19D901656G14 470-494 MHz GOLD CONTACTS 19D901656G15 489-512 MHZ GOLD CONTACTS 19D901656G16 403-425 MHZ GOLD CONTACTS
C1 19A700219P14			TO ASSURE BOARDS WITH GOLD CONTACTS ARE NOT INTERMIXED WITH BOARDS HAVING TIN CONTACTS.
C1 19A700219P14 Ceramic: 3.3 pF ±5%, 100 VDCW, temp coef 0 PPM. C2 19A700219P20 Ceramic: 22 pF ±10%, 100 VDCW, temp coef 0 PPM. C3 19A700219P20 Ceramic: 5.6 pF ±5%, 100 VDCW, NPO. C4 19A700219P20 Ceramic: 5.6 pF ±5%, 100 VDCW, temp coef 0 PPM. D1 19A702411P1 Silicon; sim to Hewlett Packard 5082-3188. L1 19A702472P3 Coil. C2 19A702061P11 Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C1 19A702061P10 Ceramic: 5.6 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1-G3, G3, G13-15 and G17). C2 19A702061P11 Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1, G2, G5, G13, G14 and G17). C3 19A702061P12 Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1 and G16). C4 19A702061P908 Ceramic: 3.9 pF ±25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G3 and G13-G15). C3 19A702061P906 Ceramic: 3.9 pF ±25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4 and G13-G15). C4 19B800873P7 Variable, ceramic: 0.5 to 2.5 pF, 150 VDCW; sim to Johanson 9620. (Used in G1-G3 and G13-G15). C5 19A702061P907 Ceramic: 2.7 pF ±25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C6 19A702061P906 Ceramic: 2.7 pF ±25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C6 19A702061P907 Ceramic: 2.7 pF ±25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C6 19A702061P907 Ceramic: 2.7 pF ±25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C7 19A702061P907 Ceramic: 2.7 pF ±25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C8 19A702061P902 Ceramic: 2.0 pF ±5%, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C8 19A702061P902 Ceramic: 1.2 pF ±25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C8 19A70236P5 Ceramic: 0.9 pF ±1 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C8 19A70236P3 Ceramic: 0.7 pF ±1 pF, 50 VDCW, 0 ±30 PPM.	A1		
C2 19A700219P40 Ceramic: 22 pF ±10%, 100 VDCW, temp coef 0 PPM. C3 19A700219P12 Ceramic: 2.7 pF ±5%, 100 VDCW, NPO. C4 19A700219P20 Ceramic: 5.6 pF ±5%, 100 VDCW, temp coef 0 PPM. D1 19A702411P1 Silicon; sim to Hewlett Packard 5082-3188. L1 19A702472P3 Coil. C2 19A702061P11 Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C2 19A702061P11 Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1-G3, G5, G13-15 and G17). C2 19A702061P12 Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C2 19A702061P12 Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C2 19A702061P12 Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C3 19A702061P908 Ceramic: 3.9 pF ±2.5 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C4 19B800873P7 Ceramic: 2.7 pF ±2.5 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C4 19B800873P8 Variable, ceramic: 0.5 to 2.5 pF, 150 VDCW; sim to Johanson 9620. (Used in G4, G5, G16 and G17). C5 19A702061P906 Ceramic: 2.7 pF ±2.5 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C6 19A702061P907 Variable, ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621. (Used in G4, G5, G16 and G17). C6 19A702061P907 Ceramic: 2.7 pF ±2.5 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C7 19A702061P907 Ceramic: 2.7 pF ±2.5 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C8 19A702061P907 Ceramic: 2.7 pF ±2.5 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C8 19A702061P902 Ceramic: 2.0 pF ±5%, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C8 19A702236P3 Ceramic: 0.9 pF ±1 pF, 50 VDCW, 0 ±30 PPM. (Used in G1 and G13). C8 19A702236P3 Ceramic: 0.7 pF ±1 pF, 50 VDCW, 0 ±30 PPM. (Used in G1 and G13).			
C3	C1	19A700219P14	Ceramic: 3.3 pF ±5%, 100 VDCW, temp coef 0 PPM.
C4	C2	19A700219P40	Ceramic: 22 pF +10%, 100 VDCW, temp coef 0 PPM.
D1 19A702411P1 Silicon; sim to Hewlett Packard 5082-3188. L1 19A702472P3 Coil. L2 19A702061P11 Coramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C1 19A702061P10 Ceramic: 5.6 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1-G3, G5, G13-15 and G17). C2 19A702061P11 Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1-G3, G5, G13, G14 and G17). C2 19A702061P12 Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1, G2, G5, G13, G14 and G17). C2 19A702061P12 Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C2 19A702061P908 Ceramic: 3.9 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G3 and G15). C3 19A702061P906 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4-G5, G16 and G17). C4 19B800873P7 Variable, ceramic: 0.5 to 2.5 pF, 150 VDCW; sim to Johanson 9620. (Used in G1-G3 and G13-G15). C4 19B800873P8 Variable, ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9620. (Used in G1-G3 and G13-G15). C5 19A702061P906 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4-G5, G16 and G17). C6 19A702061P907 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4-G5, G16 and G17). C6 19A702061P907 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4-G5, G16 and G17). C6 19A702061P907 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4-G5, G16 and G17). C8 19A702061P907 Ceramic: 2.0 pF ±5%, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4-G5, G16 and G17). C8 19A702061P902 Ceramic: 1.2 pF ±.25 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1 and G13). C8 19A70236P5 Ceramic: 0.7 pF ±1 pF, 50 VDCW, 0 ±250 PPM. (Used in G1 and G13).	СЗ	19A700219P12	Ceramic: 2.7 pF ±5%, 100 VDCW, NPO.
D1	C4	19A700219P20	Ceramic: 5.6 pF ±5%, 100 VDCW, temp coef 0 PPM.
L1 19A702472P3 Coil. Coil. 19A702472P1 Coil. Coramic: 6.8 pf ±0.5 pf, 50 VDCW, temp coef 0 ±60 PFM. (Used in G4 and G16). C1 19A702061P10 Ceramic: 5.6 pf ±0.5 pf, 50 VDCW, temp coef 0 ±60 PFM. (Used in G1-G3, G5, G13-15 and G17). C2 19A702061P11 Ceramic: 8.2 pf ±0.5 pf, 50 VDCW, temp coef 0 ±60 PFM. (Used in G1, G2, G5, G13, G14 and G17). C2 19A702061P12 Ceramic: 8.2 pf ±0.5 pf, 50 VDCW, temp coef 0 ±60 PFM. (Used in G1, G2, G5, G13, G14 and G17). C2 19A702061P908 Ceramic: 3.9 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PFM. (Used in G3 and G13). C3 19A702061P906 Ceramic: 2.7 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PFM. (Used in G1-G3 and G13-G15). C3 19A702061P907 Ceramic: 3.3 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PFM. (Used in G4, G5, G16 and G17). C4 19B800873P7 Variable, ceramic: 0.5 to 2.5 pf, 150 VDCW; sim to Johanson 9620. (Used in G1-G3 and G13-G15). C5 19A702061P906 Ceramic: 2.7 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PFM. (Used in G1-G3 and G13-G15). C6 19A702061P907 Ceramic: 2.7 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PFM. (Used in G1-G3 and G13-G15). C6 19A702061P907 Ceramic: 2.7 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PFM. (Used in G4, G5, G16 and G17). C6 19A702061P907 Ceramic: 3.3 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PFM. (Used in G4, G5, G16 and G17). C6 19A702061P907 Ceramic: 3.3 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PFM. (Used in G4, G5, G16 and G17). C6 19A702061P907 Ceramic: 3.3 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PFM. (Used in G4, G5, G16 and G17). C6 19A702061P907 Ceramic: 1.2 pf ±.25 pf, 50 VDCW, temp coef 0 ±30 PFM. (Used in G4, G5, G16 and G17). C7 (Used in G1 and G13). C8 19A702236P3 Ceramic: 0.9 pf ±.1 pf, 50 VDCW, 0 ±250 PFM. (Used in G2 and G14).			DIODES
Coil. 19A702472P1 Coil. 19A702472P1 Coil.	D1	19A702411P1	Silicon; sim to Hewlett Packard 5082-3188.
Coil. 19A702061P11 Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16).			
C1 19A702061P11 Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C1 19A702061P10 Ceramic: 5.6 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1-G3, G5, G13-15 and G17). C2 19A702061P11 Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1, G2, G5, G13-15 and G17). C2 19A702061P12 Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C2 19A702061P908 Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G3 and G15). C3 19A702061P906 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C3 19A702061P907 Ceramic: 3.3 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C4 19B800873P7 Variable, ceramic: 0.5 to 2.5 pF, 150 VDCW; sim to Johanson 9620. (Used in G1-G3 and G13-G15). C4 19B800873P8 Variable, ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621. (Used in G4, G5, G16 and G17). C5 19A702061P906 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C6 19A702061P907 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C6 19A702061P907 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C8 19A702061P902 Ceramic: 2.20 pF ±5%, 50 VDCW, temp coef 0 ±20 PPM. (Used in G4, G5, G16 and G17). C8 19A702236P5 Ceramic: 1.2 pF ±.25 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1 and G13). C8 19A702236P3 Ceramic: 0.9 pF ±.1 pF, 50 VDCW, 0 ±30 PPM. (Used in G2 and G14). C8 19A702236P3 Ceramic: 0.7 pF ±.1 pF, 50 VDCW, temp coef	L1	19A702472P3	Coil.
C1 19A702061P11 Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C1 19A702061P10 Ceramic: 5.6 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1-G3, G5, G13-15 and G17). C2 19A702061P11 Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1, G2, G5, G13, G14 and G17). C2 19A702061P12 Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C2 19A702061P908 Ceramic: 3.9 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G3 and G15). C3 19A702061P906 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C3 19A702061P907 Ceramic: 3.3 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C4 19B800873P7 Variable, ceramic: 0.5 to 2.5 pF, 150 VDCW; sim to Johanson 9620. (Used in G4, G5, G16 and G17). C4 19B800873P8 Variable, ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621. (Used in G4, G5, G16 and G17). C5 19A702061P906 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C5 19A702061P906 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C6 19A702061P907 Ceramic: 2.0 pF ±.5 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C8 19A702236P5 Ceramic: 1.2 pF ±.25 pF, 50 VDCW, temp coef 0 ±30 PPM. C8 19A702236P3 Ceramic: 0.9 pF ±.1 pF, 50 VDCW, 0 ±250 PPM. (Used in G2 and G14). C8 19A702236P3 Ceramic: 0.7 pF ±.1 pF, 50 VDCW, temp coef	L2	19A702472P1	Coil.
+60 PPM. (Used in G4 and G16). 19A702061P10 Ceramic: 5.6 pF +0.5 pF, 50 VDCW, temp coef 0 +60 PPM. (Used in G1-G3, G5, G13-15 and G17). 19A702061P11 Ceramic: 6.8 pF +0.5 pF, 50 VDCW, temp coef 0 +60 PPM. (Used in G1, G2, G5, G13, G14 and G17). 19A702061P12 Ceramic: 8.2 pF +0.5 pF, 50 VDCW, temp coef 0 +60 PPM. (Used in G4 and G16). 19A702061P908 Ceramic: 3.9 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G3 and G15). 19A702061P906 Ceramic: 2.7 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G1-G3 and G13-G15). 19A702061P907 Ceramic: 3.3 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G4, G5, G16 and G17). 19B800873P7 Variable, ceramic: 0.5 to 2.5 pF, 150 VDCW; sim to Johanson 9620. (Used in G1-G3 and G13-G15). 19A702061P906 Ceramic: 2.7 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G1-G3 and G17). 19A702061P906 Ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621. (Used in G1-G3 and G17). 19A702061P907 Ceramic: 2.7 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G1-G3 and G13-G15). 19A702061P907 Ceramic: 2.7 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G1-G3 and G13-G15). 19A702061P907 Ceramic: 3.3 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G1-G3 and G13-G15). 19A702061P907 Ceramic: 3.3 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G4, G5, G16 and G17). 19A702061P902 Ceramic: 1.2 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G4, G5, G16 and G17). 19A702236P5 Ceramic: 1.2 pF +.25 pF, 50 VDCW, 0 +250 PPM. (Used in G1 and G13). 19A702236P3 Ceramic: 0.9 pF +.1 pF, 50 VDCW, 0 +30 PPM. (Used in G2 and G14).			
C2 19A702061P11 Ceramic: 6.8 pf ±0.5 pf, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1, G2, G5, G13, G14 and G17). C2 19A702061P12 Ceramic: 8.2 pf ±0.5 pf, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C2 19A702061P908 Ceramic: 3.9 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PPM. (Used in G3 and G15). C3 19A702061P906 Ceramic: 2.7 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C3 19A702061P907 Ceramic: 3.3 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C4 19B800873P7 Variable, ceramic: 0.5 to 2.5 pf, 150 VDCW; sim to Johanson 9620. (Used in G1-G3 and G13-G15). C4 19B800873P8 Variable, ceramic: 1 to 5 pf, 150 VDCW; sim to Johanson 9621. (Used in G4, G5, G16 and G17). C5 19A702061P906 Ceramic: 2.7 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C6 19A702061P907 Ceramic: 2.7 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C6 19A702061P907 Ceramic: 2.7 pf ±.25 pf, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C6 19A702061P902 Ceramic: 220 pf ±5%, 50 VDCW, temp coef 0 ±30 PPM. C7 19A702236P5 Ceramic: 0.9 pf ±.1 pf, 50 VDCW, 0 ±250 PPM. C8 19A702236P3 Ceramic: 0.7 pf ±.1 pf, 50 VDCW, temp coef	C1	19A702061P11	
C2 19A702061P11 Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1, G2, G5, G13, G14 and G17). C2 19A702061P12 Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16). C2 19A702061P908 Ceramic: 3.9 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G3 and G15). C3 19A702061P906 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C3 19A702061P907 Ceramic: 3.3 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C4 19B800873P7 Variable, ceramic: 0.5 to 2.5 pF, 150 VDCW; sim to Johanson 9620. (Used in G1-G3 and G13-G15). C4 19B800873P8 Variable, ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621. (Used in G4, G5, G16 and G17). C5 19A702061P906 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C6 19A702061P907 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C6 19A702061P907 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C7 19A702061P902 Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. C8 19A702236P5 Ceramic: 0.9 pF ±.1 pF, 50 VDCW, 0 ±250 PPM. C8 19A702236P3 Ceramic: 0.7 pF ±.1 pF, 50 VDCW, temp coef	C1	19A702061P10	Ceramic: 5.6 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G1-G3, G5, G13-15 and G17).
#60 PPM. (Used in G4 and G16). Ceramic: 3.9 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G3 and G15). Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C3	C2	19A702061P11	
#120 PPM. (Used in G3 and G15). Ceramic: 2.7 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G1-G3 and G13-G15). Caramic: 3.3 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G4, G5, G16 and G17). Caramic: 3.3 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G4, G5, G16 and G17). Caramic: 0.5 to 2.5 pF, 150 VDCW; sim to Johanson 9620. (Used in G1-G3 and G13-G15). Caramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621. (Used in G4, G5, G16 and G17). Caramic: 2.7 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G1-G3 and G13-G15). Caramic: 3.3 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G4, G5, G16 and G17). Caramic: 220 pF +5%, 50 VDCW, temp coef 0 +120 PPM. Caramic: 220 pF +5%, 50 VDCW, temp coef 0 +30 PPM. Caramic: 1.2 pF +.25 pF, 50 VDCW, 0 +250 PPM. Caramic: 0.9 pF +.1 pF, 50 VDCW, 0 +30 PPM. Caramic: 0.9 pF +.1 pF, 50 VDCW, 0 +30 PPM. Caramic: 0.7 pF +.1 pF, 50 VDCW, temp coef	C2	19A702061P12	Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM. (Used in G4 and G16).
#120 PPM. (Used In G1-G3 and G13-G15). C23	C2	19A702061P908	Ceramic: 3.9 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G3 and G15).
#120 PPM. (Used In G4, G5, G16 and G17). Variable, ceramic: 0.5 to 2.5 pF, 150 VDCW; sim to Johanson 9620. (Used in G1-G3 and G13-G15). Variable, ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621. (Used in G4, G5, G16 and G17). C5 19A702061P906	СЗ	19A702061P906	Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1~G3 and G13-G15).
to Johanson 9620. (Used in G1-G3 and G13-G15). Variable, ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621. (Used in G4, G5, G16 and G17). C5 19A702061P906 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C6 19A702061P907 Ceramic: 3.3 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C6 19A702061P69 Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. C7 19A702061P902 Ceramic: 1.2 pF ±.25 pF, 50 VDCW, 0 ±250 PPM. (Used in G1 and GI3). C8 19A702236P5 Ceramic: 0.9 pF ±.1 pF, 50 VDCW, 0 ±30 PPM. (Used in G2 and G14). C8 19A702236P3 Ceramic: 0.7 pF ±.1 pF, 50 VDCW, temp coef	СЗ	19A702061P907	Ceramic: 3.3 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17).
C4 19B800873P8 Variable, ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621. (Used in G4, G5, G16 and G17). C5 19A702061P906 Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1-G3 and G13-G15). C6 19A702061P907 Ceramic: 3.3 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4, G5, G16 and G17). C6 19A702061P69 Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. C7 19A702061P902 Ceramic: 1.2 pF ±.25 pF, 50 VDCW, 0 ±250 PPM. C8 19A702236P5 Ceramic: 0.9 pF ±.1 pF, 50 VDCW, 0 ±30 PPM. C8 19A702236P3 Ceramic: 0.7 pF ±.1 pF, 50 VDCW, temp coef	C4	19B800873P7	Variable, ceramic: 0.5 to 2.5 pF, 150 VDCW; sim to Johanson 9620. (Used in G1-G3 and G13-G15).
#120 PPM. (Used In G1-G3 and G13-G15). C5	C4	19B800873P8	Variable, ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621. (Used in G4, G5, G16 and G17).
C6 and C7 C8 19A702061P69 Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. C8 19A702061P902 Ceramic: 1.2 pF ±.25 pF, 50 VDCW, 0 ±250 PPM. (Used in G1 and GI3). C8 19A702236P5 Ceramic: 0.9 pF ±.1 pF, 50 VDCW, 0 ±30 PPM. (Used in G2 and GI4). C8 19A702236P3 Ceramic: 0.7 pF ±.1 pF, 50 VDCW, temp coef	C5	19A702061P906	
and C7 C8 19A702061P902	C5	19A702061P907	Ceramic: 3.3 pF +.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G4, G5, G16 and G17).
(Used in G1 and G\overline{13}). C8	and	19A702061P69	
(Used in G2 and G14). C8 19A702236P3		19A702061P902	Ceramic: 1.2 pF ±.25 pF, 50 VDCW, 0 ±250 PPM. (Used in G1 and GI3).
C8 19A702236P3 Ceramic: 0.7 pF ±.1 pF, 50 VDCW, temp coef	C8	19A702236P5	
	28	19A702236P3	Ceramic: 0.7 pF ±.1 pF, 50 VDCW, temp coef

SYMBOL	GE PART NO.	DESCRIPTION
C8	19A702061P905	Ceramic: 2.2 pF ±.25 pF, 50 VDCW, 0 ±250 ppm. (Used in G4 and G16).
С8	19A702061P904	Ceramic: 1.8 pF +.25 pF, 50 VDCW, temp coef 0 +250 PPM. (Used in G5 and G17).
C9	19B800873P8	Variable, ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621.
C10 and	19A702052P14	Ceramic: 0.01 uF ±10%, 50 VDCW.
C12	19A702168P4	Variable, ceramic: 5.2 to 30 pF, 100 VDCW, temp coef N750+300 PPM; sim to JFD DV28N30D.
C13	19A702061P21	Ceramic: 15 pF +5%, 50 VDCW, temp coef 0 +30 PPM
C14	19A702061P29	Ceramic: 22 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM
C15	19A702061P33	Ceramic: 27 pF ±5%, 50 VDCW, temp coef, 0 ±30 PPM
C16	19A702061P23	Ceramic: 16 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM
C19	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1-G3 and G13-G15).
C19	19A702061P53	Ceramic: 68 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4 and G16).
C19	19A702061P65	Ceramic: 150 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in C5 and G17).
C20	19A702061P77	Ceramic: 470 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 ppM.
C21	19A700226P50	Ceramic: 39 pF ±5%, 100 VDCW, temp coef 0 -750 PPM. (Used in G1-G3, G5, G13-15 and G17).
C21	19A700227P50	Ceramic: 39 pF ±5%, 100 VDCW, temp coef 0 -1500 PPM. (Used in G4 and G16).
C22	19A700229P68	Ceramic: 120 pF ±5%, 100 VDCW, temp coef 0 -3300 PPM. (Used in G5 and G17).
C22	19A700228P59	Ceramic: 68 pF +5%, 100 VDCW, temp coef 0 -2200 PPM. (Used in G1-G3 and G13-G15).
C22	19A700228P68	Ceramic: 120 pF ±5%, 50 VDCW, temp coef 0 -2200 PPM. (Used in G4 and G16).
C23	19A702061P29	Ceramic: 22 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1 and G13).
C23	19A702061P21	Ceramic: 15 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G2, G3, G14 and G15),
C23	19A702061P35	Ceramic: 30 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4 and G16).
C23	19A702061P31	Ceramic: 24 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G5 and G17).
C24	19A702061P907	Ceramic: 3.3 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1 and G13).
C24	19A702061P909	Ceramic: 4.7 pF + 25 pF, 50 VDCW, temp coef 0 +60 PPM. (Used in G2-G5 and G14-G17).
C25	19A702168P1	Variable, ceramic: 2 to 7 pF, 100 VDCW; sim to JFD DV2SN7A.
C26	19A702061P902	Ceramic: 1.2 pF ±.25 pF, 50 VDCW, 0 ±250 PPM.
C27	19A702061P21	Ceramic: 15 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1 and G13).
C27	19A702061P17	Ceramic: 12 pF +5%, 50 VDCW, temp coef 0 +30 PPM. (Used In G2 and G14).
C27	19A702061P19	Ceramic: 13 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G3 and G15).
C27	19A702061P29	Ceramic: 22 pF +5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4 and G16).
C27	19A702061P25	Ceramic: 18 pF +5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G5 and G17).
C28	19A702061P13	Ceramic: 10 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM
C29	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.
C30	19A702061P906	Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1, G5, G13 and G17).
C30	19A702061P904	Ceramic: 1.8 pF +.25 pF, 50 VDCW, temp coef 0 +250 PPM. (Used in G2, G3 and G14 and G15).
C30	19A702061P907	Ceramic: 3.3 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G4 and G16).
C31	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.

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	SYMBOL	GE PART NO.	DESCRIPTION
	C32	19A702061P907	Ceramic: 3.3 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G1 and G13).
	C32	19A702061P906	Ceramic: 2.7 pF ±.25 pF, 50 VDCW, temp coef 0 ±120 PPM. (Used in G2, G3, G14 and G15).
	C32	19A702236P16	Ceramic: 4.3 pF \pm .25 pF, 50 VDCW, temp coef 0 \pm 30 PPM. (Used in G4 and G16).
١	C32	19A702061P908	Ceramic: 3.9 pF \pm .25 pF, 50 VDCW, temp coef 0 \pm 120 PPM. (Used in G5 and G17).
Į	C33	19A702236P6	Ceramic: 1.0 pF ±.25 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4, G5, G16 and G17).
	сзз	19A702236P1	Ceramic: 0.5 pF ±.1 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1-G3 and G13-G15).
١	C34	19A702061P903	Ceramic: 1.5 pF ±.25 pF, 50 VDCW, temp coef 0 ±250 PPM.
1	C35	19A702052P10	Ceramic: 4700 pF ±10%, 50 VDCW.
۱	C36	19A702061P37	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM
	C37	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.
	C38 thru C40	19A702052P26	Ceramic: 0.1 uF ±10%, 50 VDCW.
	C41	19A702061P13	Ceramic: 10 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM
	C42	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.
	C43	19B800755P4	Electrolytic: 10 uF ±20%, 16 VDCW.
	C44	19A702052P28	Ceramic: 0.022 uF ±10%, 50 VDCW.
	C45	19A702052P105	Ceramic: 1000 pF ±5%, 50 VDCW.
	C46	19A702052P110	Ceramic: 4700 pF ±5%, 50 VDCW.
	C47 C48	19A702052P112 19A702052P14	Ceramic: 6800 pF ±5%, 50 VDCW. Ceramic: 0.01 uF +10%, 50 VDCW.
	C48	19A702052P14 19A702052P26	Ceramic: 0.01 uF ±10%, 50 VDCW. Ceramic: 0.1 uF ±10%, 50 VDCW.
	C51	19A700003P9	Tantalum: 47 uF ±20%, 6.3 VDCW.
	C52 and C53	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.
	C54	19A702236P25	Ceramic: 10 pF ±.5 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1 and G13).
ı	C54	19A702236P23	Ceramic: 8.2 pF ±.25 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G2, G3, G14 and G15).
	C54	19A702236P28	Ceramic: 12 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4, G5, G16 and G17).
	C55	19A702236P15	Ceramic: 3.9 pF \pm .25 pF, 50 VDCW, temp coef 0 \pm 30 PPM. (Used in G1 and G13).
	C55	19A702236P23	Ceramic: 8.2 pF ±.25 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4 and G16).
	C55	19A702236P19	Ceramic: 5.6 pF ±.5 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G5 and G17).
	C56	19B800873P3	Variable, ceramic: 2.5 to 10 pF, 150 VDCW; sim to Johanson 9611.
	C57	19A702236P50	Ceramic: 100 pF <u>+</u> 5%, 50 VDCW, temp coef 0 <u>+</u> 30 PPM.
	C58	19A702236P30	Ceramic: 15 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4, G5, G16 and G17).
	C58	19A702236P25	Ceramic: 10 pF ±.5 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G2 and G14).
	C58	19A702236P23	Ceramic: 8.2 pF ±.25 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G3 and G15).
	C59	19A702236P40	Ceramic: 39 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1 and G13).
	C59	19A702236P39	Ceramic: 36 pF +.25 pF, 50 VDCW, temp coef 0 +30 PPM. (Used in G2 and G14).
	C59	19A702236P38	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G3 and G15).
	C59	19A702236P42	Ceramic: 47 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4 and G16).
	C59	19A702236P41	Ceramic: 43 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM. (Used in G5 and G17).
	C60	19A702236P41	Ceramic: 43 pF +5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G5 and G17).

SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION
C60	19A702236P40	Ceramic: 39 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1 and G13).	C89	19A702061P13	Ceramic: 10 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1, G2, G13 and G14).	C112	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 +30 PPM.	L12	19A700024P2	Coil, RF: 120 nH ±10%. (Used in G2, G3, G14 and G15).
C60	19A702236P38	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used In G3 and G15).	C89	19A702061P12	Ceramic: 8.2 pF ±0.5 pF, 50 VDCW, temp coef 0 +60 PPM. (Used in G3 and G15).				L13	1908508269322	Coil, RF: sim to Paul Smith SK-800-1.
C60	19A702236P39	Ceramic: 36 pF ± 25 pF, 50 VDCW, temp coef 0	C89	19A702061P17	Ceramic: 12 pF +5%, 50 VDCW, temp coef 0				L14	19C850826P221	Coil, RF: sim to Paul Smith SK-800-1.
C60	19A702236P42	±30 PPM. (Used in G2 and G14). Ceramic: 47 pF ±5%, 50 VDCW, temp coef 0	C90	19A702061P77	±30 PPM. (Used In G4, G5, G16 and G17). Ceramic: 470 pF +5%, 50 VDCW, temp coef 0	D1 D2	19A700155P2 19A700079P3	Silicon; sim to BBY 31.	L15	19C850826P211	Coil, RF: sim to Paul Smith SK-800-1.
		±30 PPM. (Used in G4 and G16).	and C91	13A702001F77	±30 PPM.	D4	19A702015P1	Silicon; sim to IN458A.	L16 L17	19A702213P1 19A700024P13	Coil, RF: 1.0 mH ±6%; sim to TOKO 126AN-A5318HM. Coil, RF: 1.0 uH +10%.
C61 C63	19A700003P4 19B800873P3	Tantalum: 1 uF ±20%, 35 VDCW. Variable, ceramic: 2.5 to 10 pF, 150 VDCW; sim	C92	19A702052P14	Ceramic: 0.01 uF ±10%, 50 VDCW.	and D5			L18	19A702988P1	Coil.
		to Johanson 9611.	C93	19A702061P41	Ceramic: 39 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1-G3, G5, G13-G15 and G17).	D6 and	19A700079P3	Silicon; sim to BBY 31.	L19	19A702473G1	Coil.
C65	19A702236P28	Ceramic: 12 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G2 and G14).	C93	19A702061P43	Ceramic: 43 pF ±5%, 50 VDCW, temp coef 0 +30 PPM. (Used in G4 and G16).	D7 D8	19A702015P2	Silicon; sim to IN458A.	L20	19A702472P8 19A700024P13	Coil. Coil, RF: 1.0 uH +10%.
C65	19A702236P35	Ceramic: 24 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4 and G16).	C94	19A702061P25	Ceramic: 18 pF +5%, 50 VDCW, temp coef 0	D9	19A700079P3	Silicon; sim to BBY 31.	L22	19A702472P3	Coil.
C65	19A702236P34	Ceramic: 22 pF +5%, 50 VDCW, temp coef 0 +30 PPM. (Used in G5 and G17).	C94	19A702061P33	±30 PPM. (Used In C1-G3 and G13-G15). Ceramic: 27 pF +5%, 50 VDCW, temp coef 0	D10	19A700155P2	Silicon; sim to Bat 18.	L24	19A700024P13	Coil, RF: 1.0 uH ±10%.
C65	19A702236P30	Ceramic: 15 pF +5%, 50 VDCW, temp coef 0			±30 PPM. (Used in G4 and G16).				L25	19A700024P1	Coil, RF: 100 nH ±10%, 0.08 chms DC res max, 100 v.
C66	19A702236P50	±30 PPM. (Used in G1, G3, G13 and G15). Ceramic: 100 pF +5%, 50 VDCW, temp coef 0	C94	19A702061P29	Ceramic: 22 pF +5%, 50 VDCW, temp coef 0 +30 PPM. (Used in G5 and G17).	F1	19A702169P9	Enclosed link: rated 3 amps @ 125 v; sim to Littelfuse 255003.	L26	19A702474P4	Coil.
C67	19A703324P2	±30 PPM.	C95	19A702061P45	Ceramic: 47 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1-G3, G5, G13-G15 and G17).			JACKS	L27	19A700024P1	Coil, RF: 100 nH ±10%, 0.08 ohms DC res max, 100 v.
C68	19A703324P2	Electrolytic: 2.2 uF <u>+</u> 20%, 50 VDCW. Ceramic: 1000 pF +10%, 50 VDCW.	C95	19A702061P49	Ceramic: 56 pF +5%, 50 VDCW, temp coef 0 +30 PPM. (Used in G4 and G16).	J1	19B801108G1	Connector, coax: BNC Series, 500 VRMS.	L28	19A700024P13	Coil, RF: 1.0 uH ±10%.
C70	19A702168P2	Variable, cermic: 3 to 11 pF 100 VDCW, temp coef N450+300 PPM; sim to JFD DV28N11C.	C96	19A702061P906	Ceramic: 2.7 pF +.25 pF, 50 VDCW, temp coef 0	J2 and	19A703248P4	Contact, electrical. (Quantity 7 each). (Groups 1-5).	L29 and	19A702474P5	Coil.
C71	19A702236P25	Ceramic: 10 pF +.5 pF, 50 VDCW, temp coef 0			+120 PPM. (Used In G1, G2, G5, G13, G14 and G17).	13			L30 L31	19A700024P13	Coil, RF: 1.0 uH +10%.
C71	19A702236P30	±30 PPM. (Used in G1, G2, G5, G13, G14 and G17). Ceramic: 15 pF ±5%, 50 VDCW, temp coef 0	C96	19A702061P905	Ceramic: 2.2 pF ±.25 pF, 50 VDCW, temp coef 0 ±250 PPM. (Used in G3 and G15).	J2 and J3	19A703248P14	Contact, electrical. (Groups 13-17).	L32	19A702474P1	Coil.
		±30 PPM. (Used in G4 and G16).	C96	19A702061P907	Ceramic: 3.3 pF ±.25 pF, 50 VDCW, temp coef 0 +120 PPM. (Used in G4 and G16).	J4	19A703248P1	Contact, electrical. (Quantity 4).	L33	19A700024P13	Coil, RF: 1.0 uH ±10%.
C71	19A702236P23	Ceramic: 8.2 pF ±.25 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G3 and G15).	C97	19A702061P35	Ceramic: 30 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1 and G13).	J5 and	19A703248P1	Contact, electrical.	L34 and	19C850826P212	Coil, RF: sim to Paul Smith SK-800-1.
C72	19A702061P45	Ceramic: 47 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM	C97	19A702061P33	Ceramic: 27 pF +5%, 50 VDCW, temp coef 0	J6			L35 L36	19C850826P612	Coil, RF; sim to Paul Smith SK-800-1.
C73	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.	C97	19A702061P41	<u>+</u> 30 PPM. (Used In G2, G3, G14 and G15). Ceramic: 39 pF ±5%, 50 VDCW, temp coef 0	18 18	19A703248P1 19A703248P4	Contact, electrical. Contact, electrical.	L37	19C850826P312	Coil, RF: sim to Paul Smith SK-800-1.
C74	19A702052P14	Ceramic: 0.01 uF ±10%, 50 VDCW.			±30 PPM. (Used in G4 and G16).	J10	19A703248P1	Contact, electrical.	F38	19A700024P6	Coil. (Used in G1, G2, G13 and G14).
C75	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.	C97	19A702061P39	Ceramic: 36 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G5 and G17).	J12 and	19A703248P1	Contact, electrical.	L38	19A700024P5 19A700024P9	Coil, RF: 220 nH ±10%. (Used in G3 and G15).
C76	19A702061P45	Ceramic: 47 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM	C98	19A700227P50	Ceramic: 39 pF ±5%, 100 VDCW, temp coef 0 -1500 PPM. (Used in G1, G4, G5, G13, G16 and	J13		- AMPLIANCE -	L38	19A700024P9	Coil, RF: 470 nH ±10%. (Used in G4 and G16). Coil, RF: 390 nH ±10%. (Used in G5 and G17).
C78	19A702168P1	Variable, ceramic: 2 to 7 pF, 100 VDCW; sim to JFD DV2SN7A.	C98	19A700226P50	G17). Ceramic: 39 pF +5%, 100 VDCW, temp coef 0	L1	19A702472P32		L39	19A703602G1	Coil, RF. Includes 19B800827P24 tuning slug.
C79	19A702061P3	Ceramic: 1.5 pF ±0.5 pF, 50 VDCW, temp coef 0 ±250 PPM.	1		-750 PPM. (Used in G2 and G14).	L1	19A702472P33	Coil. (Used in G4, G5, G16 and G17).	L40	19A700024P13	Coil, RF: 1.0 uH ±10%.
C80	19A702061P7	Ceramic: 3.3 pF ±0.5 pF, 50 VDCW, temp coef 0 ±120 PPM.	C98	19A700228P50	Ceramic: 39 pF ±5%, 50 VDCW, temp coef 0 -2200 PPM. (Used in G3 and G15).	L1	19A702472P3	Coil. (Used in G1 and G13).	L42	19A703602G1 19A700024P13	Coil, RF. Includes 19B800827F24 tuning slug. Coil, RF: 1.0 uH +10%.
C81	19A702168P1	Variable, ceramic: 2 to 7 pF, 100 VDCW; sim to	C99	19A700229P68	Ceramic: 120 pF ±5%, 100 VDCW, temp coef 0 -3300 PPM. (Used in G1, G2, G13 and G14).	L2 L3	19A702472P30 19C850826P211	Coil. Coil, RF: sim to Paul Smith SK-800-1.	L44	19A702472P34	Coil. (Used in G2, G3, G14 and G15).
C82	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0	C99	19A700227P68	Ceramic: 120 pF ±5%,50 VDCW, temp coef 0 -1500 PPM. (Used in G3 and G15).	L4	19A702472P3	Coil. (Used in G1, G2, G4, G5, G13, G14, G16 and	1.44	19A702472P7	Coil. (Used in G1, G4, G5, G13, G16 and G17).
C83	19A702052P14	±30 PPM. Ceramic: 0.01 uF ±10%, 50 VDCW.	C99	19A700228P68	Ceramic: 120 pF ±5%, 50 VDCW, temp coef 0	and L5		G17).	L45	19A703161P2	Coil. (Used in G1, G2, G4, G5, G13, G14, G16 and G17).
C84	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0	C99	19A700230P68	-2200 PPM. (Used in G4 and G16). Ceramic: 120 pF ±5%, 50 VDCW, temp coef 0	L4 and	19A702472P32	Coil. (Used in G3 and G15).	L45	19A703161P1	Coil. (Used in G3 and G15).
C85	19A702061P41	±30 PPM. Ceramic: 39 pF ±5%, 50 VDCW, temp coef 0	C100	19A702052P3	-4200 PPM. (Used in G5 and G17). Ceramic: 470 pF ±10%, 50 VDCW.	L5 L6	19A700024P15	Coil, RF: 1.5 uH +10%.	L46 L48	19A700024P13	Coil, RF: 1.0 uH ±10%.
	·	±30 PPM. (Used in G1-G3, G5, G13-G15 and G17).	C101	19A702052P3	Ceramic: 470 pr ±10%, 50 VDCW. Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0	L7	19A700024P13	Coil, RF: 1.0 uH ±10%. (Used in G1-G3 and	and L49	19B801465P1	Coil, RF.
C85	19A702061P43	Ceramic: 43 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4 and G16).	and C102		±30 PPM.	and L8		G13-G15).	L50	19A700024P13	Coil, RF: 1.0 uH ±10%.
C86	19A702061P29	Ceramic: 22 pF +5%, 50 VDCW, temp coef 0 +30 PPM. (Used in G1-G3 and G13-G15).	C103	19A702236P6	Ceramic: 1.0 pF ±.25 pF, 50 VDCW, temp coef 0 ±30 PPM.	L7 and	19A700024P14	Coil, RF: 1.2 uH ±10%. (Used in G4, G5, G16 and G17).			
C86	19A702061P37	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4, G5, G16 and G17).	C106	19B800650P15	Tantalum: 3.3 uF ±20%, 10 VDCW.	L9	19A700024P11	Coil, RF: 680 nH ±10%. (Used in G1, G2, G13 and	Q1	19A702413P2	Silicon, NPN; sim to Phillips BFR92.
C87	19A702061P41	Ceramic: 39 pF +5%, 50 VDCW, temp coef 0	C108	19A700219P18	Ceramic: 4.7 pF $\pm 5\%$, 100 VDCW, temp coef 0 PPM. (Used in G2, G3, $\overline{\rm G}14$ and G15).			G14).	Q2	19A703795P1	N Type: field effect; sim to MMBF4416.
C87	194702061P37	±30 PPM. (Used in G1 and G13). Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0	C108	19A700219P22	Ceramic: 6.8 pF ±5%, 100 VDCW, temp coef 0 PPM. (Used in G1, G4, G5, G13, G16 and G17).	L9 L9	19A700024P10 19A700024P13	Coil, RF: 560 nH ±10%. (Used in G3 and G15). Coil, RF: 1.0 uH ±10%. (Used in G4 and G16).	Q3 Q4	19A700092P2 19A700236P4	Silicon, NPN. Silicon, NPN.
C87		±30 PPM. (Used in G2, G3, G14 and G15).	C109	19A116192P14	Ceramic: 0.1 uF ±20%, 50 VDCW; sim to Erie USCC	L9	19A700024P12	Coil, RF: 820 nH ±10%. (Used in G5 and G17).	Q5	19A700238P4 19A700092P2	Silicon, NPN.
	19A702061P47	Ceramic: 51 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4 and G16).	C110	19A702236P25	CW20C104-M2. Ceramic: 10 pF +.5 pF, 50 VDCW, temp coef 0	L10	19A702472P24	Coil.	ଦ୍ର	19A700076P2	Silicon, NPN.
C87	19A702061P43	Ceramic: 43 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used In G5 and G17).			Ceramic: 10 pF ±.5 pF, 50 VDCW, temp coef 0 ±30 PPM. (Used in G1, G2, G5, G13, G14 and G17).	L11	19A702472P26	Coil. (Used in G1, G4, G5, G13, G16 and G17).	Q7 and	19A700026P1	Silicon, PNP.
C88	19A702061P7	Ceramic: 3.3 pF ±0.5 pF, 50 VDCW, temp coef 0 ±120 PPM.	C110	19A702236P30	Ceramic: 15 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (Used in G4 and G16).	L11 L12	19A702472P25 19A700024P3	Coil. (Used in G2, G3, G14 and G15). Coil, RF: 150 nH ±10%. (Used in G1, G4, G5,	Q8 Q9	19A702448P1	Silicon, NPN; sim to 2N5945.
		-						G13, G16 and G17).	Q10	19A701940P3	Silicon, NPN; sim to SRF-516.
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R41 198006077471 Metal film: 470 ohms ±5%, 200 VDCW, 1/8 w. Max	ontact, electrical: sim to AMP 2-332070-2. ontact, electrical: sim to AMP 2-330808-8.
R42 19801281P471 Composition: 470 ohms ±5%, 150 VDCW, 1/8 w. and XY5 Ave and Q13 194700026P1 Silicon, NPN. R44 198800607P100 Metal film: 10 ohms ±5%, 200 VDCW, 1/8 w. Z1 194702522G11 Crystand Q15 Crystand Q15 Crystand Q15 R45 198800607P100 Metal film: 10 ohms ±5%, 200 VDCW, 1/8 w. Z2 Crystand Q15 Crystand Q1	
Q12 19A700236P4 Silicon, NFN.	
Q13	
R45 19B800607P101 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R47 19B800607P102 Metal film: 10 ohms ±5%, 200 VDCW, 1/8 w. R48 19B800607P103 Metal film: 10 ohms ±5%, 200 VDCW, 1/8 w. R51 19B800607P103 Metal film: 10 ohms ±5%, 200 VDCW, 1/8 w. R52 19B800607P103 Metal film: 10 ohms ±5%, 200 VDCW, 1/8 w. R53 19B800607P103 Metal film: 10 ohms ±5%, 200 VDCW, 1/8 w. R54 19B800607P103 Metal film: 22 ohms ±5%, 200 VDCW, 1/8 w. R55 19B800607P103 Metal film: 5.6% ohms ±5%, 200 VDCW, 1/8 w. R56 19B800607P272 Metal film: 2.7% ohms ±5%, 200 VDCW, 1/8 w. R57 19B800607P105 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R58 19B800607P107 Metal film: 10% ohms ±5%, 200 VDCW, 1/8 w. R59 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R50 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R51 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R52 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R50 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R50 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R51 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R52 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R53 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R54 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R55 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R56 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R57 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R58 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R59 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R50 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R57 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R58 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R59 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R50 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R51 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R52 19B800607P103 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R59 1	
R45 19B800607P101 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. Z2 19A702171P1 Band CPUC R1 19B800607P122 Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 2.7K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 2.7K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 2.7K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. Metal f	rystal pair. (Includes Z2).
R1 19800607P122 Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. R2 19A702585P99 Composition: 33K ohms ±5%, 150 VDCW, 1/8 w. R3 19B800607P123 Metal film: 12K ohms ±5%, 200 VDCW, 1/8 w. R4 19B800607P332 Metal film: 2.7K ohms ±5%, 200 VDCW, 1/8 w. R5 19B800607P332 Metal film: 2.7K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R7 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R7 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film	Part of Z1).
R1	andpass filter: 455 ±1.5 kHz; sim to Murata FU455D2.
R1 19B800607P122 Metal film: 1.2K ohms ±5%, 200 VDCW, 1/8 w. R2 19A702585P99 Composition: 33K ohms ±5%, 150 VDCW, 1/8 w. R3 19B800607P123 Metal film: 12K ohms ±5%, 200 VDCW, 1/8 w. R4 19B800607P332 Metal film: 3.3K ohms ±5%, 200 VDCW, 1/8 w. (Used in G1, G2, G4, G13, G14 and G16). R5 19B800607P272 Metal film: 2.7K ohms ±5%, 200 VDCW, 1/8 w. (Used in G3, G5, G15 and G17). R5 19B800607P30 Metal film: 10K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P30 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R7 19B800607P750 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P750 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 1.5K ohms ±5%,	miscellaneous
R2 19A702585P99 Composition: 33K ohms ±5%, 150 VDCW, 1/8 w. R3 19B800607P123 Metal film: 12K ohms ±5%, 200 VDCW, 1/8 w. R4 19B800607P332 Metal film: 3.3K ohms ±5%, 200 VDCW, 1/8 w. (Used in G1, G2, G4, G13, G14 and G16). R5 19B800607P272 Metal film: 2.7K ohms ±5%, 200 VDCW, 1/8 w. (Used in G3, G5, G15 and G17). R5 19B800607P30 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P150 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R7 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P750 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R7 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R7 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 15 ohms ±5%, 200 VDCW, 1/8 w.	rvstal pad. (Used in Z1 & Z2).
R3	crew, thread forming: No. 1-64 x 7/32.
R5	Secures J1 mounting).
R4 19B800607P272 Metal film: 2.7K ohms ±5%, 200 VDCW, 1/8 w. (Used in G3, G5, G15 and G17). R5 19B800607P750 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R57 19B800607P102 Metal film: 10K ohms ±5%, 200 VDCW, 1/8 w. R58 19B800607P102 Metal film: 1K ohms ±5%, 200 VDCW, 1/8 w. R59 19B800607P50 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R59 19B800607P102 Metal film: 56 ohms ±5%, 200 VDCW, 1/8 w. R59 19B800607P102 Metal film: 56 ohms ±5%, 200 VDCW, 1/8 w. R59 19B800607P102 Metal film: 1K o	hield.
R5 19B800607P750 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R6 19B800607P152 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R7 19B800607P750 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 1K ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 56 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 56 ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 1K ohms ±5%, 200 VDCW, 1/8 w. R8 19B800607P102 Metal film: 1K ohms ±5%, 200 VDCW, 1/8 w.	attery Pack. 7.5 Volt.
R6 19B800607P152 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w. R7 19B800607P750 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R60 19B800607P102 Metal film: 1K ohms ±5%, 200 VDCW, 1/8 w. R60 19B800607P102 Metal film: 1K ohms ±5%, 200 VDCW, 1/8 w. R60 19B800607P102 Metal film: 1K ohms ±5%, 200 VDCW, 1/8 w.	attery Pack. 10 voit.
R7 19B800607P750 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. R60 19B800607P102 Metal film: 1K ohms ±5%, 200 VDCW, 1/8 w	ASSOCIATED PARTS
R60 19B800607P102 Metal film: 1K ohms ±5%, 200 VDCW, 1/8 w	
R8 19B800607P152 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w.	
R9 exac	OTE: when reordering specify GE part number and xact frequency needed.
	x = Fo - 21.4
	uartz.
(Used in G4, G5, G16 and G17). R65 19B800607P562 Metal film: 5.6K ohms ±5%, 200 VDCW, 1/8 w. Y2	
R11 19B800607P220 Metal film: 22 ohms ±5%, 200 VDCW, 1/8 w. (Used in G1-G3 and G13-G15).	$x = \frac{Fo}{8}$
ALL INDUCTION MOUNT IN THE TOTAL TOT	uartz: 20945.000 kHz
	Alternate IF Crystal) 21855.0 kHz.
	uartz.
P14 198906079750 Metal film: 75 ohme +5% 200 VDCW 1/8 w P70 1988006079220 Metal film: 22 ohms +5% 200 VDCW 1/8 w.	
R15 19B800607P561 Metal film: 560 ohms +5%, 200 VDCW, 1/8 w. R71 19B800607P223 Metal film: 22K ohms +5%, 200 VDCW, 1/8 w.	MISCELLANEOUS
(Used in G1-G3 and G13-G15). R72 19B800607P152 Metal film: 1.5K ohms ±5%, 200 VDCW, 1/8 w.	hip antenna. (403-470 MHz).
(Used in G4. G5. G16 and G17). R73 19B800751P16 Variable, solid carbon: 100K ohms +25%, 0.05 w;	hip antenna. (470-494 MHz). hip antenna. (489-512 MHz).
R16 19B800607P104 Metal film: 100K ohms ±5%, 200 VDCW, 1/8 w. R74 19B801251P222 Composition: 2.2K ohms ±5%, 150 VDCW, 1/8 w.	ary uncommut (100 012 mile).
R17 19B800607P123 Metal film: 12K ohms ±5%, 200 VDCW, 1/8 w. R77 19B800607P223 Metal film: 22K ohms ±5%, 200 VDCW, 1/8 w.	
R18 19B800607P750 Metal film: 75 ohms ±5%, 200 VDCW, 1/8 w. (Used in G1-G3 and G13-G15).	
R19 19B800607P101 Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. R77 19B800607P183 Metal film: 18K ohms ±5%, 200 VDCW, 1/8 w. (Used in G4, G5, G16 and G17).	
R20 19B800607P102 Metal film: 1K ohms ±5%, 200 VDCW, 1/8 w. R78 19B800607P823 Metal film: 82K ohms ±5%, 200 VDCW, 1/8 w. (Used in G4, G5, G16 and G17).	
R22 19B800607P103 Metal film: 10K ohms +5%, 200 VDCW, 1/8 w. R78 19B800607P683 Metal film: 68K ohms ±5%, 200 VDCW, 1/8 w.	
R23 19B800607P822 Metal film: 8.2K ohms +5%, 200 VDCW, 1/8 w. (Used in G1-G3 and G13-G15).	
R79 19B800607P473 Metal film: 47K ohms ±5%, 200 VDCW, 1/8 w.	
R25 19B800607P222 Metal film: 2.2K ohms ±5%, 200 VDCW, 1/8 w. R80 19B800607P823 Metal film: 82K ohms ±5%, 200 VDCW, 1/8 w. R81 19B800607P123 Metal film: 12K ohms ±5%, 200 VDCW, 1/8 w.	
and R81 19B800607P123 Metal film: 12K ohms ±5%, 200 VDCW, 1/8 W.	
R27 19B800607P473 Metal film: 47K ohms ±5%, 200 VDCW, 1/8 w.	
R28 19B800607P223 Metal film: 22K ohms ±5%, 200 VDCW, 1/8 w. S1 (Part of R38).	<u> </u>
R29 19B800607P153 Metal film: 15K ohms ±5%, 200 VDCW, 1/8 w. S2 19A702244P1 Slide switch: DPDT, contact rating 1 mA @ 19R800607P563 Metal film: 56K ohms +5%, 200 VDCW, 1/8 w. S2 19A702244P1 Slide switch: DPDT, contact rating 1 mA @ 10 VDC; sim to Alps SSS02200.	
	•
R31 19B800607P682 Metal film: 6.8K ohms ±5%, 200 VDCW, 1/8 w INTEGRATED CIRCUITS INTEGRATED CIRCUITS INTEGRATED CIRCUITS INTEGRATED CIRCUITS	
.1 w; sim to TOCOS RPR124. U1 19A701780P1 Linear: IF AMPLIFIER AND DETECTOR.	
R34 19B800607P563 Metal film: 56K ohms ±5%, 200 VDCW, 1/8 w. U2 19D438002G1 5.4 Volt Voltage Regulator.	
R35 19B800607P823 Metal film: 82K ohms ±5%, 200 VDCW, 1/8 w.	
R36	
R37 19B800607P821 Metal Illm: 520 onms ±5%, 200 vbcw, 1/8 w. and XY2	

PARTS LIST

PARTS LIST

FRONT COVER
19D900647G1 STANDARD
19D900647G2 LICENSEE
19D900647G4 CGE OPTION
ISSUE 5

HARDWARE KIT
19A702379G1 SINGLE MULTI FREQ
19A702379G2 UHF
19A702379G3 HIGH BAND
ISSUE 5

PARTS LIST

GE PART NO.

19A704779P56

SYMBOL

P2 and P3

DESCRIPTION

Printed wire: 7 contacts rated @ 2.5 amps; Gold Plated Contacts. (Groups 7 and 8 only).

AUDIO BOARD
19D901123G1 STANDARD
19D901123G2 DTMF
19D901123G7 STANDARD (GOLD CONTACTS)
19D901123G8 DTMF (GOLD CONTACTS)

									· Q2	19A700026P1	Silicon, PNP.
SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION	Q3 thru Q7	19A700076P2	Silicon, NPN.
		SPEAKERS AND MIKES						NOTE: WHEN CHANGING BOARDS, CARE SHOULD BE TAKEN	Q8	19A700059P2	Silicon, PNP.
в1	19A134460P1							TO ASSURE BOARDS WITH GOLD CONTACTS ARE NOT	Q9	19A700076P2	Silicon, NPN.
	198134400F1	Loudspeaker, permanent magnet: 2 inches, 8 ohms + or - 10%, imp 500 mW, 450 + or -100 Hz resonant freg; sim to Pioneer A50AP13-01F.		19A702471P3	Crystal pad. (Used with Y3).			INTERMIXED WITH BOARDS HAVING TIN CONTACTS. REPLACE ONLY WITH SAME GROUP NUMBER AS THE ORIGINAL.	Q10	19A702760P1	P type, field effect.
В2	19J706041P1	Microphone cartridge: 200-850 ohms output imp.,		19A702471P2	Crystal pad. (Used with Y1, Y2, Y4, Y5).			URIGINAL.			- 5775, 12524 5215501
52	13070004111	1.5 to 10 VDC; sim to Primo EM-60.		19A702332P1	Nut, slotted: M7 x .75. (Secures R32 & S1).	1					
				19B800849P1	Washer, rectangular. (Located between ON-OFF switch and housing).	C1	19A702052P120	Ceramic: 0.033 uF <u>+</u> 5%, 50 VDCW.	R1	19B800607P333	Metal film: 33K ohms ±5%, 200 VDCW, 1/8 w.
C1	19A700232P64	Ceramic: 100 pF + or -10%, 100 VDCW, temp coef		19A702314P2	Knurled nut. (Secures J11).	C2 and	19A702052P112	Ceramic: 6800 pF ±5%, 50 VDCW.	R2	19B800607P683	Metal film: 68K ohms ±5%, 200 VDCW; 1/8 w.
and C2		-5600 PPM.	}	19A703007P212	Machine screw, Torx drive: M2.545 x 12.	C3		'	R3	19B800607P393	Metal film: 39K ohms ±5%, 200 VDCW, 1/8 w.
СЗ	19B800650P13	Tantalum: 1 uF -20+40%, 10 VDCW.			(Secures rear cover below nameplates).	C4	19A702052P128	Ceramic: 0.022 uF ±5%, 50 VDCW.	R4	19B800607P333	Metal film: 33K ohms ±5%, 200 VDCW, 1/8 w.
				19A702362P208	Machine screw, Torx drive: M2.545 x 8. (Secures rear cover at top).	C5	19A702052P12	Ceramic: 6800 pF ±10%, 50 VDCW.	R5 and R6	19B800607P473	Metal film: 47K ohms ±5%, 200 VDCW, 1/8 w.
				19B800859P1	Knob, push on.	C6	19A702844P1	Tantalum: 22 uF ±20%, 6.3 VDCW.	R7	10000000000150	W
P4	10.700.05-1	Connector. Includes:	1	19A702364P104	Machine screw, Torx®Drive: M2-0.4 x 4. (Secures	C7	19A702052P10	Ceramic: 4700 pF ±10%, 50 VDCW.	R8	19B800607P153 19B800607P821	Metal film: 15K ohms ±5%, 200 VDCW, 1/8 w.
	19A702405P4	Shell.			option cover).	C8	19A702052P4	Ceramic: 680 pF +10%, 50 VDCW.	R9	19B800607P821	Metal film: 820 ohms ±5%, 200 VDCW, 1/8 w.
Wl	19A702405P28	Contact, electrical.		19A700032P1	Lockwasher, internal tooth: No. 2. (Secures option cover).	C9	19A702052P26	Ceramic: 0.1 uF ±10%, 50 VDCW.	R10	19B800607P180	Metal film: 15K ohms ±5%, 200 VDCW, 1/8 w.
WI	19B800860G1	Cable assembly. (Includes P4)		19D900667P1	Option Cover.	C10	19B800755P7	Electrolytic: 100 uF ±20%, 10 VDCW.	R11	19B800607P104	Metal film: 18 ohms ±5%, 200 VDCW, 1/8 w.
		MISCELLANEOUS		N248P15B	Hex nut.	C11	19B800755P4	Electrolytic: 10 uF ±20%, 16 VDCW.	R13	19A702289P1	Metal film: 100K ohms ±5%, 200 VDCW, 1/8 w.
	19A702396P1	Nameplate. (GENERAL ELECTRIC).				C12 and	19A702052P26	Ceramic: 0.1 uF <u>+</u> 10%, 50 VDCW.	1 110	13410226371	Metal film: 1 ohms ±5%, 1/4 w; sim to Corning FL55.
	19C850975P1	Insulator.				C13	10470990401	Floatmalation OR at 100% 16 MDGW	R14	19B800607P471	Metal film: 470 ohms ±5%, 200 VDCW, 1/8 w.
	19A703346P1	Pad.		\		C14	19A703324P1 19A702052P107	Electrolytic: 22 uF ±20%, 16 VDCW.	R15	19B800607P472	Metal film: 4.7K ohms ±5%, 200 VDCW, 1/8 w.
	19A149342P3	Pad.				C15	19A702032P107	Ceramic: 2200 pF +5%, 50 VDCW.	R16	19B800607P183	Metal film: 18K ohms ±5%, 200 VDCW, 1/8 w.
						C16	19A701334P4 19A702061P61	Tantalum: 1 uF ±20%, 35 VDCW.	R17	19B800607P683	Metal film: 68K ohms ±5%, 200 VDCW, 1/8 w.
		İ				617	194702061961	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.	R18	19B800607P473	Metal film: 47K ohms ±5%, 200 VDCW, 1/8 w.
						C18	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.	R19	19B800607P562	Metal film: 5.6K ohms ±5%, 200 VDCW, 1/8 w.
])		C19	19B800755P4	Electrolytic: 10 uF ±20%, 16 VDCW.	R20	19B800607P183	Metal film: 18K ohms ±5%, 200 VDCW, 1/8 w.
						C20	19A702052P122	Ceramic: 0.047 uF <u>+</u> 5%, 50 VDCW.	R21	19B800607P472	Metal film: 4.7K ohms ±5%, 200 VDCW, 1/8 w.
						C21	19A702052P110	Ceramic: 4700 pF ±5%, 50 VDCW.	R22	19B800607P331	Metal film: 330 ohms ±5%, 200 VDCW, 1/8 w.
			1	1		C22 and	19A702052P122	Ceramic: 0.047 uF ±5%, 50 VDCW.	R23	19B800607P821	Metal film: 820 ohms ±5%, 200 VDCW, 1/8 w.
					l	C23			R24	19B800607P104	Metal film: 100K ohms ±5%, 200 VDCW, 1/8 w.
		·				C24	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM. (G2 and G8 only).	R25	19B800607P473	Metal film: 47K ohms ±5%, 200 VDCW, 1/8 w.
		ì		ļ		C25	19A702052P106	Ceramic: 1500 pF ±5%, 50 VDCW.	R26	19B800607P823	Metal film: 82K ohms ±5%, 200 VDCW, 1/8 w.
						C26	19B800755P2	Electrolytic: 2.2 uF ±20%, 50 VDCW.	R27	19B800607P473	Metal film: $47K$ ohms $\pm 5\%$, 200 VDCW, $1/8$ w. (G2 and G8 only).
			1			C27	19A702061P77	Ceramic: 470 pF +5%, 50 VDCW, temp coef 0	R28	19B800607P224	Metal film: 220K ohms ±5%, 200 VDCW, 1/8 w.
	·							±30 PPM.	R29	19B800607P823	Metal film: 82K ohms ±5%, 200 VDCW, 1/8 w.
			1			C28	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 +30 PPM.	R30	19B800607P274	Metal film: 270K ohms ±5%, 200 VDCW, 1/8 w.
	ļ		.			C30	19B800755P2	Electrolytic: 2.2 uF ±20%, 50 VDCW.	R31	19B800607P103	Metal film: 10K ohms ±5%, 200 VDCW, 1/8 w.
						and C31		<u> </u>	R32	19B800607P223	Metal film: 22K ohms ±5%, 200 VDCW. 1/8 w.
						C32	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0	R33	19B800607P183	Metal film: 18K ohms ±5%, 200 VDCW, 1/8 w.
			1					±30 PPM.	R34	19B800607P333	Metal film: 33K ohms ±5%, 200 VDCW, 1/8 w.
						C33	19A702052P26	Ceramic: 0.1 uF ±10%, 50 VDCW.	R35	19B800607P103	Metal film: 10K ohms ±5%, 200 VDCW, 1/8 w.
					*	C37	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.	R36	19B800607P223	Metal film: 22K ohms ±5%, 200 VDCW; 1/8 w.
				l					R37	19B800607P183	Metal film: 18K ohms ±5%, 200 VDCW, 1/8 w.
								DIODES	R38	19A701828P1	Thermistor: 3.3K ohms +5%; sim to Philips
						D1 and	19A700028P1	Silicon, fast recovery: fwd current 75 mA, 75 PIV; sim to Type 1N4148.	P30	100000000000	2322-642-63332,
						D2			R39	19B800607P124	Metal film: 120K ohms ±5%, 200 VDCW, 1/8 w.
									R40	19B800607P273	Metal film: 27K ohms ±5%, 200 VDCW, 1/8 w.
						P2 and P3	19A700041P56	Printed wire: 7 contacts rated @ 2.5 amps; sim to Molex 22-02-2075. (Groups 1 and 2 only).	R41	19B800607P224	Metal film: 220K ohms ±5%, 200 VDCW, 1/8 w.
					LETED OR CHANGED BY PRODUCTION CHANGES.			LETED OR CHANGED BY PRODUCTION CHANGES.			

SYMBOL	GE PART NO.	DESCRIPTION
R42	19B800607P223	Metal film: 22K ohms +5%, 200 VDCW, 1/8 w.
R43	19B800607P473	Metal film: 47K ohms +5%, 200 VDCW, 1/8 w.
R44	19B800607P102	Metal film: 1K ohms ±5%, 200 VDCW, 1/8 w.
R45	19B800607P471	Metal film: 470 ohms ±5%, 200 VDCW, 1/8 w.
υı	19A702410p1	Linear: Audio Amplifier; sim to TBA-820M
	19A701622P1	Cotter pin. (Located between Rl5 & Rl9 - G2 and G8 only).
	19A149342P1	Pad.
	19A149342P2	Pad.
	19A705029P1	Crystal boot.
	19A705029P2	Crystal boot.

PARTS LIST

SIDE PANEL 19D900646G1 1 FREQ 19D900646G3 2 FREQ ISSUE 3

PARTS LIST

REAR COVER
19D901087G1 HB HIGH POWER
19D901087G2 UHF HIGH POWER
19D901087G3 HB LOW POWER
19D901087G4 UHF LOW POWER

PARTS LIST

SIDE PANEL 19D901089G1 1 FREQ 19D901089G2 2 FREQ ISSUE 2

					PD901087G4 UHF LOW POWER ISSUE 1			
SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION
81	19B800847P1 19B800864G1	Push switch: contacts rated 25 mA @ 9 VDC; sim to Bowmar KB3256-1D.	P1	19B800852P1 19A701728P2 19A701488P2	Connector. Includes: Contact, electrical. Washer, non-metallic. Retaining ring.	J1 and J2	19A703304P1 19B800847P1	Telephone jack: rated 1/8 amp @ 125 VAC; sim to Switchcraft MDSL-280.
	19C850854P1 19A702460P1 19A702471P6 19A703672P1	Slide button. Contact, electrical. (Quantity 2). Crystal Pad. Switch stop. (G1 only).	P2	19B216401P5 19B800851P1 19B800852P1 19B701728P2 19B701488P2	Spring. Insulator. Connector. Includes: Contact, electrical. Washer, non-metallic; Retaining ring.		19A702461P1 19B800864G1 19C850854P1	Screw, thread forming: No. 0-40 x 1/4. (Secures slide button). Pushbutton. Slide button.
			P3 and P4	19B216401P5 19A702405P26 19C850865P1	Spring. Contact, electrical: rated @ 3 amps. MISCELLANEOUS Option receptacle.		19A702460P1 19B232415P1 19A703672P1 19A702471P6	Contact, electrical. (Used with S1). Bushing. Switch stop. Crystal pad.
				N327P9008E 19A702471P6 19C850861P2	Rivet, tubular. Foam pad. Insulator, glass epoxy			
					,			

PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter," which is stamped after the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for descriptions of parts affected by these revisions.

REV. A - TRANSMITTER/RECEIVER BOARD 19D901656G1-5

To improve dependability of transmitter when voltage drops below 7.5 volts. Changed R48.

R48 was 19B800607P101 - Metal film: 100 ohms 5%, 1/8W.

REV. B - To facilitate manufacturing. Changed interconnect pins from solder mount to stake mount. This is a factory change to all system boards manufactured after 1/10/86.

REV. C - TRANSMITTER/RECEIVER BOARD 19D901656G1~4 REV. A - TRANSMITTER/RECEIVER BOARD 19D901656G13-16

To prevent RF amplifier from oscillating while tuning C9 and C4. Changed R4. To facilitate manufacturing. Changed C86 and Q10.

R4 was: 19B800607P30 - Metal film: 3.3K ohms 5%, 1/8W. Q10 was: 19A701940P3 - Silicon, NPN. Q86 was: 19A702061P3 - Ceramic: 33 pF 5%, 50 VDCW.

FOR CANADIAN GE ONLY
REV. E - AUDIO BOARD 19D901123G1,3

To prevent audio from squealing when transmitter is keyed and microphone is rubbed against operator's cheek. Added C201, C202, and C203 to High Band modification Kit (19A703929G1). Schematics have been revised to show location of components. See partial schematics and instructions for modification kit.

REV D TRANSMITTER/RECEIVER BOARD 19D901656G1-4
REV C TRANSMITTER/RECEIVER BOARD 19D901656G5
REV B TRANSMITTER/RECEIVER BOARD 19D901656G13-16
REV A TRANSMITTER/RECEIVER BOARD 19D901656G17
To improve system operation, changed electrical contacts.

Part was 19A702752P2 Eletrical Contact.

REV C - TRANSMITTER/RECEIVER BOARD 19D901656G3
REV C - TRANSMITTER/RECEIVER BOARD 19D901656G15

To improve power output of the UHF Transmitter Board, changed C65. To improve SINAD, changed C8.

C65 was: 19A702236P21 - Ceramic: 6.8 pF \pm .5 pF, 50 VDCW, temp coef 0 \pm 60 PPM.

C8 was: 19A702236P3 - Ceramic: .7 pF + .1 pF, 50 VDCW, temp coef 0 + 30 PPM.



GE Mobile Communications

MPI® PERSONAL RADIO

CHANNEL GUARD DIGITAL CHANNEL GUARD CARRIER CONTROL TIMER

Maintenance Manual

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CHANNEL GUARD (CG)

DESCRIPTION

The MPI Channel Guard is a continuous-tone encoder and decoder for operation on tone frequencies in the 71.9 to 210.7 Hz range. Both the encoder and decoder operate on the same frequency. The option consists of a Channel Guard module and an option board. The option board provides the proper interface with the transmitter-receiver board.

The Channel Guard module contains a tone frequency synthesizer, encoder, decoder and Squelch Tail Eliminator circuitry (see Figure 1). The synthesizer is programmable to produce Channel Guard tones from 67 to 210.7 Hz in 0.25 Hz increments.

The synthesizer uses a crystal controlled 32,768 Hz reference to produce the desired clock inputs to the encoder and decoder circuits and produce digitally generated time delays for the STE circuitry.

The Channel Guard circuit is controlled by an CG-OFF switch on the control unit. Placing the switch in the OFF position disables the decoder circuits to permit monitoring all calls on the channel. Placing the switch in the CG position enables the Decoder.

CIRCUIT ANALYSIS

ENCODE

When the transmit circuit is keyed, the CPTT lead is pulled low and the

Channel Guard module responds by pulling the DPTT lead low, holding the transmit circuit in a keyed condition. The encoder circuit generates a sine wave encoder tone which passes through a low pass filter to remove any clock and tone harmonics. This output tone is connected by the CG output lead to the transmitter audio circuit.

When the radio is unkeyed, the CPTT lead goes high but the PTT delay circuit holds the transmit circuit in a keyed condition for an additional 160 milliseconds by holding the DPTT lead low during this time. During this 160 millisecond time, the encode circuit sends the tone with a 135° phase shift. This combination of 135° phase shift and 160 millisecond delay causes the CG decoder in other receivers to squelch the receiver audio prior to loss of RF signal. This reduces or eliminates the receiver noise burst.

DECODE

In the decode mode, receiver audio from the quadrature detector is applied to the CG module where it passes through a 212 Hz low pass filter to remove voice information. This prevents voice falsing or clipping in the decoder circuit. The digital decoder compares the frequency of the incoming tone to a reference clock produced by the synthersizer. If the correct tone is detected, the module responds by releasing the RUS (Receiver UnSquelched) lead which is normally held in a low voltage condition when the correct tone is not detected.

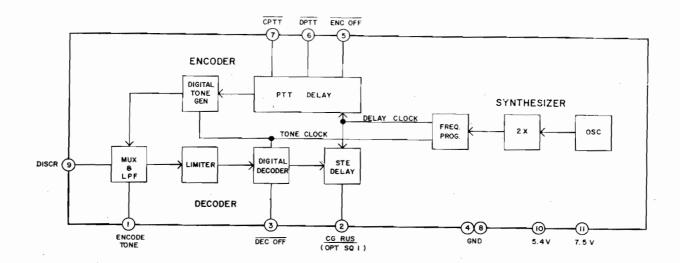


Figure 1 - Channel Guard Module

After decoding the tone, the decoder then looks for a phase shift to occur. If the phase shift occurs, the decoder responds by pulling CG RUS low for 200 milliseconds using the STE delay circuit. This forces the receive circuit to squelch for 200 ms during which time the received carrier should disappear.

DIGITAL CHANNEL GUARD (DCG)

DESCRIPTION

The DCG module contains three integrated circuits consisting of a system linear circuit, an encoder circuit and a decoder circuit (see Figure 2).

The system linear circuit contains the required analog circuits, including a crystal controlled slow clock oscillator circuit, a free running fast clock oscillator circuit, a limiter circuit, for received audio, active filter components and system interfacing.

CIRCUIT ANALYSIS

ENCODE

The encoder circuit is programmed to produce a repetitive, twenty-three bit binary word. This binary word can be one

of 83 possible codes between 023 and 754 (see DCG Programming Procedure). The programming is accomplished by nine programming pins located on the top of the module.

When the transmit circuit is keyed, the CPTT lead is pulled low and the Digital Channel Guard module responds by pulling the DPTT lead low, holding the transmit circuit in a keyed condition. The encoder circuit generates a repetitive twenty-three code word, using the slow 32 kHz clock, which passes through a low pass filter (Digital Code Filter) to remove any high frequency components. The digital output is connected by the CG Encode lead to the transmit audio circuit.

When the radio is unkeyed, the CPTT lead goes high, but the PTT delay circuit holds the transmit circuit in a keyed condition for an additional 180 milliseconds by holding the DPTT lead low during this time. During this 180 milliseconds delay, the digital word generator generates a 135 Hz sine wave. This transmitted sine wave and the 180 millisecond delay causes the DCG decoder in other receivers to squelch the receiver circuit audio prior to loss of RF signal. This reduces or eliminates the receiver noise burst.

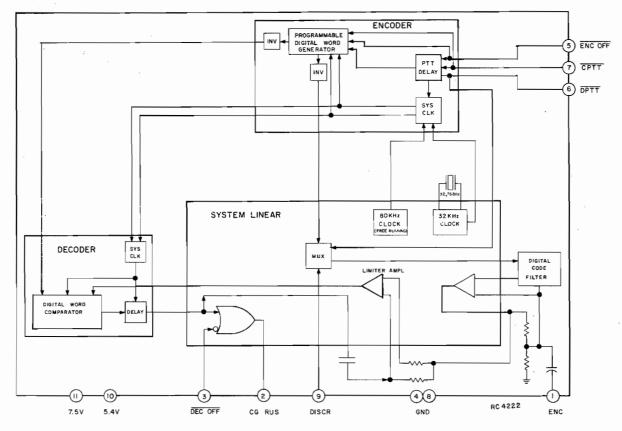


Figure 2 - Digital Channel Guard Module

DECODE

In the decode mode, receiver audio from the quadrature detector lead is fed to the DCG module where it passes through a 212 Hz low pass filter to remove voice information. This prevents interference in detecting the correct code word in the decoder circuit. The decoder circuit compares the digital code word received by the receive circuit to the digital code word generated by the digital word generator. All possible combinations of the code word are check to insure the correct code word is detected. Comparisons are made at the fast 80 kHz clock rate for a fast response time. The module responds by releasing the RUS lead normally held in a low voltage condition

when the correct code word is not detected. Releasing the RUS lead unsquelches the receive circuit.

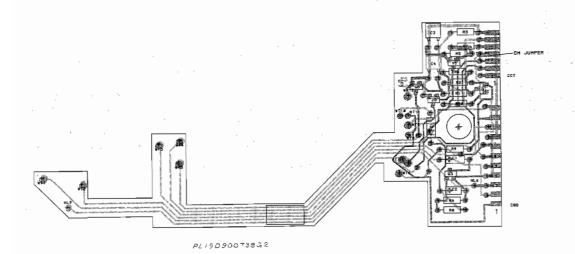
CARRIER CONTROL TIMER

DESCRIPTION

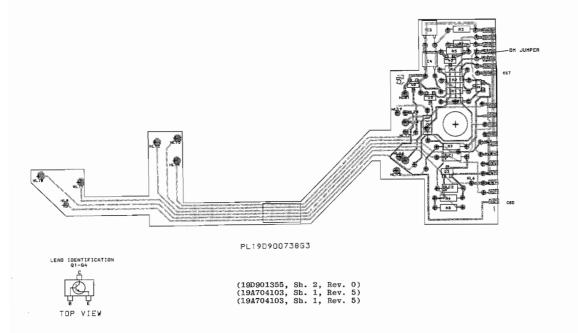
MPI Carrier Control Timer automatically interrupts the transmission of a transmitter by deactivating the system PTT after a 70 second ±10 seconds timing cycle. The timer also alerts the operator that the transmitter is off with a 950 Hertz alarm tone from the speaker as long as the push-to-talk switch is pressed. Transmission can be resumed by releasing the push-to-talk switch and re-keying the transmitter.



GE Mobile Communications



(19D901355, Sh. 1, Rev. 3) (19A704103, Sh. 1, Rev. 5) (19A704103, Sh. 2, Rev. 5)



OUTLINE DIAGRAM

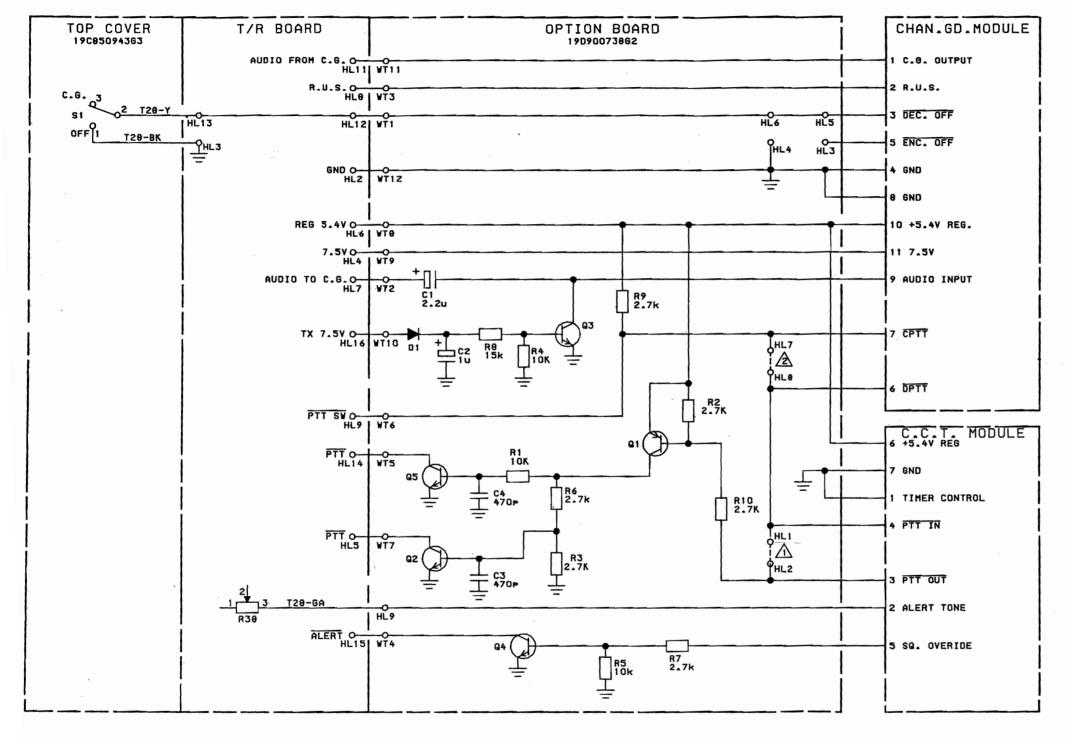
OPTION BOARD FOR CHANNEL GUARD AND CARRIER CONTROL TIMER

Issue 2

- RUNS ON SOLDER SIDE

RUNS ON COMPONENT SIDE

RUNS ON BOTH SIDES



(19D901356, Sh. 1, Rev. 5)

NOTES

⚠ JUMPER FOR NON CCT UNITS.

JUMPER FOR CCT ONLY UNITS.

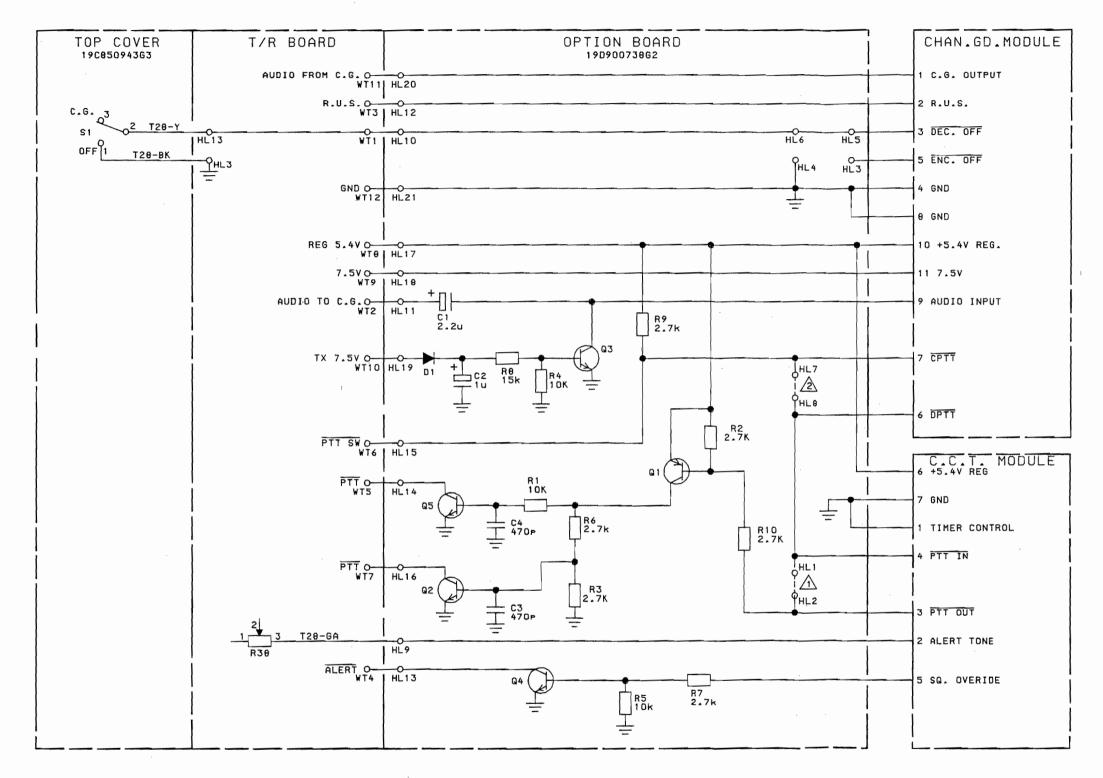
NOTE: NO JUMPERS ARE USED FOR COMBINATION CG AND CCT UNITS.

ALL RESISTORS ARE 1/8 WATT UNLESS OTHERWISE SPECIFIED.
RESISTOR VALUES IN OUNLESS FOLLOWED BY MULTIPLIER & OR M.
CAPACITOR VALUES IN F UNLESS FOLLOWED BY MULTIPLIER DOR P.
INDUCTANCE VALUES IN H UNLESS FOLLOWED BY MULTIPLIER DOR D.

MODEL NO.	REV.	LETTER	
PL19D900738G2			
}			

SCHEMATIC DIAGRAM

Channel Guard and Carrier Control Timer 19D900738G2



NOTES:

1 JUMPER FOR NON CCT UNITS.

JUMPER FOR CCT ONLY UNITS.

NOTE: NO JUMPERS ARE USED FOR COMBINATION CG AND CCT UNITS.

ALL RESISTORS ARE 1/8 WATT UNLESS OTHERWISE SPECIFIED.
RESISTOR VALUES IN \(\Omega\) UNLESS FOLLOWED BY MULTIPLIER k OR M.
CAPACITOR VALUES IN F UNLESS FOLLOWED BY MULTIPLIER m OR p.
INDUCTANCE VALUES IN H UNLESS FOLLOWED BY MULTIPLIER m OR p.

MODEL NO.	REV.	LETTER	
PL19D900738G3			
			- 1
			- 1

SCHEMATIC DIAGRAM

Channel Guard and Carrier Control Timer 19D900738G3

(19D901356, Sh. 2, Rev. 1)

PARTS LIST

MPI OPTION BOARD 19D900738G1-G4 ISSUE 6

я.
DCW.
to Sprague
CW.
DCW.
CW.
DCW.
in series).
150 VDCW, 1/8 w.
200 VDCW, 1/8 w.
150 VDCW, 1/8 w.
150 VDCW, 1/8
200 VDCW, 1/8
150 VDCW 1/9 w
150 VDCW, 1/8 w.
150 VDCW, 1/8 200 VDCW, 1/8
150 VDCW, 1/8 w.
200 VDCW, 1/8 w.
150 VDCW, 1/8 w.
200 VDCW, 1/8 w.
150 VDCW, 1/8
200 VDCW, 1/8
150 VDCW, 1/8
200 VDCW, 1/8
150 VDCW, 1/8 w.
,

*COMPONENTS ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES.

SYMBOL	GE PART NO.	DESCRIPTION
R8 R9	19B800607P153 19A702585P73	Metal film: 15K ohms + or - 5%, 200 VDCW, 1/8 w. Composition: 2.7K ohms + or -5%, 150 VDCW, 1/8
R9	19B800607P272	Wetal film: 2.7K ohms + or - 5%, 200 VDCW, 1/8
R10	19A702585P73	W. Composition: 2.7K ohms + or -5%, 150 VDCW, 1/8
R10	19B800607P272	Wetal film: 2.7K ohms + or - 5%, 200 VDCW, 1/8
R11	19B800607P1	w. Metal Film: 0 ohms (50 Milli-ohms Max), 1/8 w.
		- ~ WIRE TAPS
	19A702752Pl	Contact.
	19A702471P6	Foam pad. (Located on printed board 19D900739P1).
ĺ		
	l	

PARTS LIST

CARRIER CONTROLLED TIMER
AND
CHANNEL GUARD HARDWARE KIT
19A702765G1 CARRIER CONTROLLED TIMER
19A702765G2 CHANNEL GUARD ENCODER
19A702765G3 CHANNEL GUARD ENCODER/DECODER
19A702765G4 CHANNEL GUARD ENCODER/DECODER
ISSUE 5

SYMBOL	GE PART NO.	DESCRIPTION
	19D900738G4	MPI Option Board.
	19B219681P1	Contact, electrical. (Located on terminals 0-9 to program CG freg. or DCG Code).
	19D429521P1	Cover. (Located over Channel Guard select pins).
	19C850943G3	Top Cover.
	19D900667P1	Option Cover.
	19A702364P104	Machine screw, TORX Drive: M2-0.4 x 4.
	19A700032P1	Lockwasher, internal tooth: No. 2.
	19A702471P6	Xtal Pad.
	19B800865G3	Top Cover. Channel Guard.
ľ	19D429618G5	1 Tone Channel Guard - Encode Module.
	19D429618G6	1 Tone Channel Guard - Encode/Decode Module.
	19C327619G1	Carrier Controlled Timer
	19D432621G10	l Code Digital Channel Guard (Negative Phase) Module.
'		

^{*}COMPONENTS ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES.

PRODUCTION CHANGES

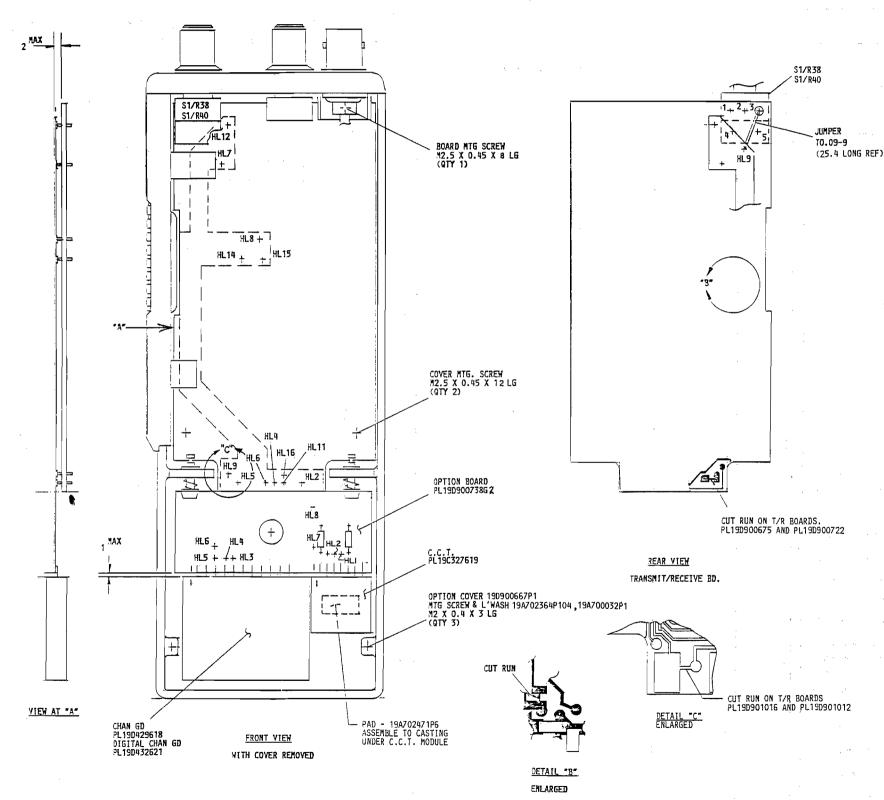
Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter," which is stamped after the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for descriptions of parts affected by these revisions.

REV. A - Option Board 19D900738G2

Incorporated in initial shipment.

REV. B - Option Board 19D900738G2

To correct reverse squelch tail on radios with Carrier Control Timer. Added C4, $\ensuremath{\mathrm{Q5}}$ and $\ensuremath{\mathrm{R10}}$.



INSTALLATION INSTRUCTIONS

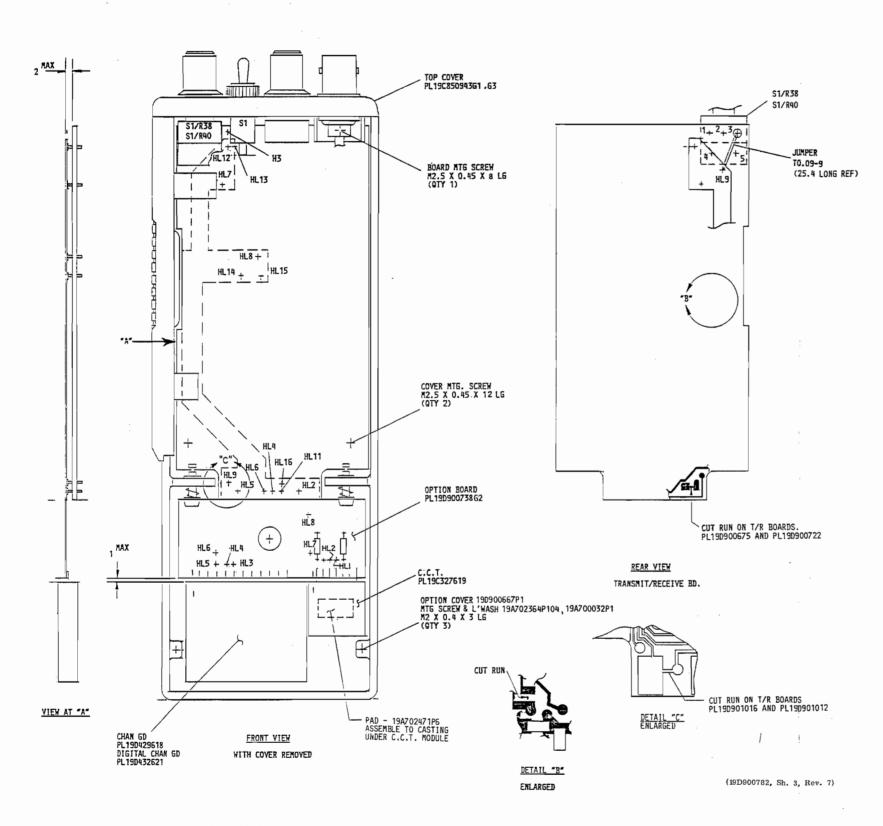
(19D900782, Sh. 1, Rev. 6)

8

Issue 2

- THESE INSTRUCTIONS COVER THE INSTALLATION OF CHAN. GD. KIT PL19A702765G1 FOR APPLICATION OF CARRIER CONTROL TIMER TO MPI PERSONAL RADIO
 - REMOVE BATTERY PACK, FRONT COVER AND OPTION COVER. REMOVE SCREW FROM ANTENNA MOUNTING BRACKET AND REMOVE TOP COVER AND TRANSMIT/RECEIVE BOARD AS AN ASSEMBLY.
 - 2. ON TRANSMIT/RECEIVE BOARD CUT RUNS AS SHOWN. (2 PLACES).
 - 3. SOLDER C.C.T. MODULE TO OPTION BOARD AS SHOWN.
 - SOLDER JUMPER FROM HL9 ON OPTION BOARD TO S1/R38-3 OR S1/R40-3 ON SOLDER SIDE OF TRANSMIT/RECEIVE BOARD. ROUTE JUMPER BETWEEN OPTION BOARD AND T/R BOARD. REMOVE DM JUMPER FROM HLI TO HL2 ON OPTION BOARD. BOARD. ADD DM JUMPER FROM HLT TO HL8 ON OPTION BOARD.
 - ALIGN PINS ON OPTION BOARD WITH CORRESPONDING HOLES ON TRANSMIT/RECEIVE BOARD. SEAT FULLY AND SOLDER. MAX ASSEMBLED HEIGHT TO BE 2 BELOW TRANSMIT/RECEIVE BOARD
 - REASSEMBLE TRANSMIT/RECEIVE BOARD, TOP COVER, REAR COVER, OPTION COVER, FRONT COVER, AND BATTERY PACK.
- THESE INSTRUCTIONS COVER THE INSTALLATION OF CHAN, GD. KIT PL19A702765G2 FOR APPLICATION OF CHANNEL GUARD/DIGITAL CHANNEL GUARD ENCODE ONLY TO MPI PERSONAL RADIO
 - REMOVE BATTERY PACK. FRONT COVER AND OPTION COVER. REMOVE SCREW FROM ANTENNA MOUNTING BRACKET AND REMOVE TOP COVER AND TRANSMIT/RECEIVE BOARD AS AN ASSEMBLY.
 - 2. ON TRANSMIT/RECEIVE BOARD CUT RUNS AS SHOWN, (2 PLACES).
 - SOLDER DESIRED CHANNEL GUARD MODULE TO OPTION BOARD AS SHOWN. SEE SHEETS 4 OR 5 FOR CODING INSTRUCTIONS.
 - 4. ON DIGITAL CHANNEL GUARD ONLY-SOLDER DA JUMPER FROM HL4 TO HL5 ON
 - 5. ALIGN PINS ON OPTION BOARD WITH CORRESPONDING HOLES ON TRANSMIT/RECEIVE BOARD. SEAT FULLY AND SOLDER. MAX ASSEMBLED HEIGHT TO BE 2 BELOW TRANSMIT/RECEIVE BOARD
 - ★ 6. REASSEMBLE TRANSMIT/RECEIVE BOARD, TOP COVER, REAR COVER, OPTION COVER; FRONT COVER, AND BATTERY PACK.
- THESE INSTRUCTIONS COVER THE INSTALLATION OF CHAN. GD. KIT PL19A702765G2 FOR APPLICATION OF CHANNEL GUARD/DIGITAL CHANNEL GUARD ENCODE ONLY AND CARRIER CONTROL TIMER TO M.P.I. PERSONAL RADIO
 - * 1. REMOVE BATTERY PACK, FRONT COVER AND OPTION COVER. REMOVE SCREW FROM ANTENNA MOUNTING BRACKET AND REMOVE TOP COVER AND TRANSMIT/ RECEIVE BOARD AS AN ASSEMBLY.
 - 2. ON TRANSMIT/RECEIVE BOARD CUT RUNS AS SHOWN. (2 PLACES).
 - SOLDER DESIRED CHANNEL GUARD MODULE AND CARRIER CONTROL TIMER MODULE TO OPTION BOARD AS SHOWN. SEE SHEETS 4 OR 5 FOR CODING INSTRUCTIONS.
 - SOLDER JUMPER FROM HL9 ON OPTION BOARD TO S1/R38-3 OR S1/R40-3 ON SOLDER SIDE OF TRANSMIT/RECEIVE BOARD.ROUTE JUMPER BETWEEN OPTION BOARD AND T/R BOARD.REMOVE DM JUMPER FROM HL1 TO HL2 CN OPTION BOARD. ON DIGITAL CHANNEL GUARD ONLY-SOLDER DA JUMPER FROM HL4 TO HL5 ON OPTION ALIGN PINS ON OPTION BOARD WITH CORRESPONDING HOLES ON BOARD TRANSMIT/RECEIVE BOARD. SEAT FULLY AND SOLDER. MAX ASSEMBLED HEIGHT TO BE 2 BELOW TRANSMIT/RECEIVE BOARD

 - REASSEMBLE TRANSMIT/RECEIVE BOARD; TOP-COVER, REAR COVER; OPTION COVER, FRONT COVER, AND BATTERY PACK.
 - * APPLIES ONLY IF OPTION IS INSTALLED IN AN ASSEMBLED RADIO.



INSTALLATION INSTRUCTIONS

Issue 2 10

- THESE INSTRUCTIONS COVER THE INSTALLATION OF CHAN. GD. KIT PL19A70276563.64 FOR APPLICATION OF CHANNEL GUARD/DIGITAL CHANNEL GUARD ENCODE ONLY WITH OFF/ON SWITCH AND CARRIER CONTROL TIMER TO MPI PERSONAL RADIO
 - * 1. REMOVE BATTERY PACK, FRONT COVER AND OPTION COVER. REMOVE SCREW FROM ANTENNA MOUNTING BRACKET AND REMOVE TOP COVER AND TRANSMIT/ RECEIVE BOARD AS AN ASSEMBLY.
 - *2. REMOVE KNOBS & NUTS SECURING TOP COVER TO TRANSMIT/RECEIVE BOARD POTS, REMOVE EXISTING TOP COVER, BEFORE ASSEMBLING NEW TOP COVER PL19C850943G1,G3 MAKE THE FOLLOWING CONNECTIONS.

FROM	TO	WIR
S1-1	HL3	BK
S1-2	HL13	Y

- 3. ON TRANSMIT/RECEIVE BOARD CUT RUNS AS SHOWN, (2 PLACES).
- SOLDER DESIRED CHANNEL GUARD MODULE AND CARRIER CONTROL TIMER MODULE TO OPTION BOARD AS SHOWN. SEE SHEETS 4 OR 5 FOR CODING
- 5. ON OPTION BOARD CUT RUN BETWEEN HLS & HL6 AS SHOWN.
- 6. MAKE THE FOLLOWING CONNECTIONS ON THE OPTION BOARD

FROM	TO	WIRE	REMARKS
HL4	HL5	DA	DIGITAL CHANNEL GUARD ONLY
HE3	_HL6	DA	
HLI	HL2	DM	REMOVE

- SOLDER JUMPER FROM HL9 ON OPTION BOARD TO S1/R38-3 OR S1/R40-3 ON SOLDER SIDE OF TRANSMIT/RECEIVE BOARD.ROUTE JUMPER BETWEEN OPTION BOARD AND T/R BOARD.
- TREASON OPTION BOARD WITH CORRESPONDING HOLES ON TRANSMIT/RECEIVE BOARD. SEAT FULLY AND SOLDER. MAX ASSEMBLED HEIGHT TO BE 2 BELOW TRANSMIT/RECEIVE BOARD.
- *9. REASSEMBLE TRANSMIT/RECEIVE BOARD. TOP COVER, REAR COVER. OPTION COVER. AND BATTERY PACK.
- THESE INSTRUCTIONS COVER THE INSTALLATION OF CHAN. GD. KIT PL19A70276563.64 FOR APPLICATION OF CHANNEL GUARD/DIGITAL CHANNEL GUARD ENCODE/DÉCODE WITH MONITOR SWITCH AND CARRIER CONTROL TIMER TO MPI PERSONAL RADIO
 - *1. REMOVE BATTERY PACK, FRONT COVER AND OPTION COVER. REMOVE SCREW FROM ANTENNA MOUNTING BRACKET AND REMOVE TOP COVER AND TRANSMIT/RECEIVE BOARD AS AN ASSEMBLY.
 - *2. REMOVE KNOBS & NUTS SECURING TOP COVER TO TRANSMIT/RECEIVE BOARD POTS, REMOVE EXISTING TOP COVER. BEFORE ASSEMBLING NEW TOP COVER PL19C850943G1.G3 MAKE THE FOLLOWING CONNECTIONS.

S1-1	HL3 HL13	BK
S1-2	HL13	Υ

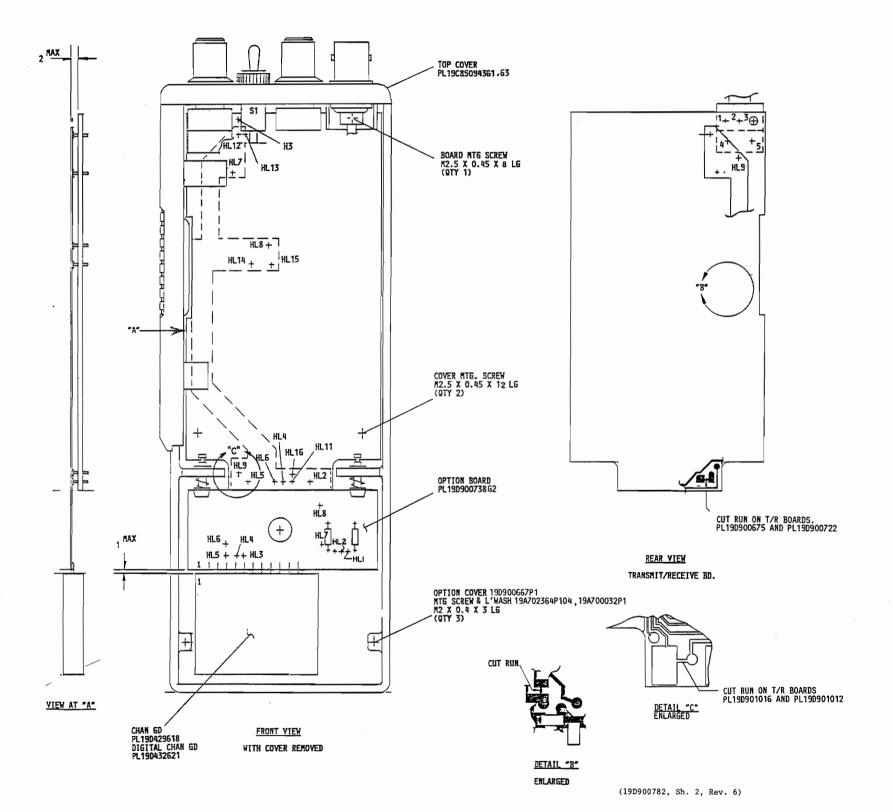
WIRE

3. ON TRANSMIT/RECEIVE BOARD CUT RUNS AS SHOWN, (2 PLACES).

FROM

- SOLDER DESIRED CHANNEL GUARD MODULE AND CARRIER CONTROL TIMER MODULE TO OPTION BOARD AS SHOWN. SEE SHEETS 4 OR 5 FOR CODING INSTRUCTIONS.
- 5. SOLDER JUMPER FROM HL9 ON OPTION BOARD TO S1/R38-3 OR S1/R40-3 ON SOLDER SIDE OF TRANSMIT/RECEIVE BOARD.ROUTE JUMPER BETWEEN OPTION BOARD AND T/R BOARD.REMOVE DM JUMPER FROM HLI TO HL2 ON OPTION BOARD.

 6. ALIGN PINS ON OPTION BOARD WITH CORRESPONDING HOLES ON TRANSMIT/RECEIVE BOARD. SEAT FULLY AND SOLDER. MAX ASSEMBLED HEIGHT TO BE 2 BELOW TRANSMIT/RECEIVE BOARD.
- ★ 7. REASSEMBLE TRANSMIT/RECEIVE BOARD, TOP COVER, REAR COVER, OPTION COVER, AND BATTERY PACK.
- * APPLIES ONLY IF OPTION IS INSTALLED IN AN ASSEMBLED RADIO



LBI31392

- THESE INSTRUCTIONS COVER THE INSTALLATION OF CHAN; GD. KIT PL:19A70276563,G4 FOR APPLICATION OF CHANNEL GUARD/DIGITAL CHANNEL GUARD ENCODE ONLY. WITH OFF/ON SWITCH TO MPI PERSONAL RADIO
 - * 1. REMOVE BATTERY PACK, FRONT COVER AND OPTION COVER. REMOVE SCREW FROM ANTENNA MOUNTING BRACKET AND REMOVE TOP COVER AND TRANSMIT/ RECEIVE BOARD AS AN ASSEMBLY.
 - *2. REMOVE KNOBS & NUTS SECURING TOP COVER TO TRANSMIT/RECEIVE BOARD POTS, REMOVE EXISTING TOP COVER. BEFORE ASSEMBLING NEW TOP COVER PL19C850943G1,G3 MAKE THE FOLLOWING CONNECTIONS.

ROM	TO	WIRE
1-1 1-2	HL3 HI 13	BK

- 3. ON TRANSMIT/RECEIVE BOARD CUT RUNS AS SHOWN. (2 PLACES)
- SOLDER DESIRED CHANNEL GUARD MODULE TO OPTION BOARD AS SHOWN. SEE SHEETS 4 OR 5 FOR CODING INSTRUCTIONS.
- 5. ON OPTION BOARD CUT RUN BETWEEN HLS & HL6 AS SHOWN.
- 6. MAKE THE FOLLOWING CONNECTIONS ON THE OPTION BOARD

FROM	то	WIRE	REMARKS
HL4	HL5	DA	DIGITAL CHANNEL GUARD ONLY
HL3	HLF	DA	

- ALIGN PINS ON OPTION BOARD WITH CORRESPONDING HOLES ON TRANSMIT/RECEIVE BOARD. SEAT FULLY AND SOLDER. MAX ASSEMBLED HEIGHT TO BE 2 BELOW TRANSMIT/RECEIVE BOARD.
- * 8. REASSEMBLE TRANSMIT/RECEIVE BOARD, TOP COVER, REAR COVER, OPTION COVER, AND BATTERY PACK.
- THESE INSTRUCTIONS COVER THE INSTALLATION OF CHAN. GD. KIT PL19A70276563.64
 FOR APPLICATION OF CHANNEL GUARD/DIGITAL CHANNEL GUARD ENCODE/DECODE.
 WITH MONITOR SWITCH TO MPI PERSONAL RADIO
 - *1. REMOVE BATTERY PACK, FRONT COVER AND OPTION COVER. REMOVE SCREW FROM ANTENNA MOUNTING BRACKET AND REMOVE TOP COVER AND TRANSMIT/ RECEIVE BOARD AS AN ASSEMBLY.
 - *2. REMOVE KNOBS & MUTS SECURING TOP COVER TO TRANSMIT/RECEIVE BOARD POTS, REMOVE EXISTING TOP COVER. BEFORE ASSEMBLING NEW TOP COVER PL19C850943G1,G3 MAKE THE FOLLOWING CONNECTIONS.

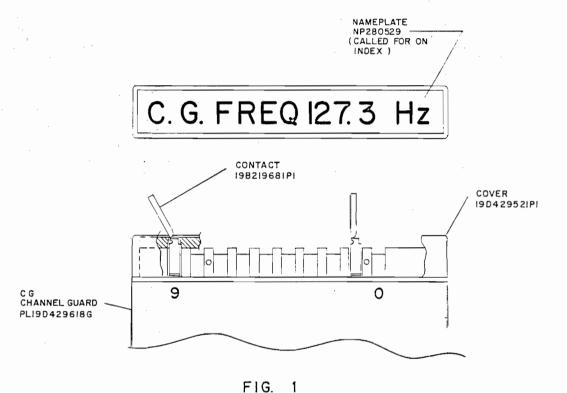
FROM	TO	WIRE
\$1-1	HL3	.BK
\$1-2	HL13	Y

- 3. ON TRANSMIT/RECEIVE BOARD CUT RUNS AS SHOWN, (2 PLACES).
- SOLDER DESIRED CHANNEL GUARD MODULE TO OPTION BOARD AS SHOWN. SEE SHEETS 4 OR 5 FOR CODING INSTRUCTIONS.
- 5 ALIGN PINS ON OPTION BOARD WITH CORRESPONDING HOLES ON TRANSMIT/RECEIVE BOARD. SEAT FULLY AND SOLDER. MAX ASSEMBLED HEIGHT TO BE 2 BELOW TRANSMIT/RECEIVE BOARD.
- ★ 6. REASSEMBLE TRANSMIT/RECEIVE BOARD_TOP_COVER, REAR_COVER. OPTION COVER, AND BATTERY PACK.
- * APPLIES ONLY IF OPTION IS INSTALLED IN AN ASSEMBLED RADIO.

INSTALLATION INSTRUCTIONS

Issue 2

9



THESE INSTRUCTIONS COVER THE FREQ COOING FOR C. G. MODULE 190429618 USING THE STANDARD C. G. FREQ.

- INSTALL CONTACT PINS (198219681), PER FIG. 1, IN POSITIONS INDICATED BY "X" IN CHART 1. WHICH AGREES WITH DESIRED CG FREQ. (NOTE EXAMPLE SHOWN FOR 127.3Hz).
- 2. ASSEMBLE SNAP ON COVER (190429521P1).
- BREAK OFF CONTACT TABS ABOVE COVER BY BENDING TOWARD EITHER END OF MODULE. (DO NOT BEND TAB TOWARD SIDE OF MODULE).
- STAMP APPROPRIATE CG FREQ ON LABEL (NP280529) AND ASSEMBLE IN RECESS ON TOP OF COVER. (EXAMPLE 127.3)

CHART I

C.G.										FREQ CHART									
	L	CO	NTA	CT	PIN	PC	SIT	ION	1										
FREQ	9	8	7	6	5	4	3	2	I	0									
67	X		Х	Х	X	X			X	X									
71.9	Х		Х	Х		Х	Х	X	X	X									
77	Х		Х	Х			X		Х	Х									
82.5	Х		Х	Ĺ	Х	X		X		X									
88.5	Х		Х			Х	X	Х		X									
94.8	Х		Х					Х	ĺ										
100	Х	Ĺ.,		Х	Х		X	Х	Х	Х									
103.5	Х			X	X					Х									
107.2	Х			X		X			Х										
110.9	Χ			Х					Х	Х									
114.8	Х				Х	Х		Х											
118.8	Х				Х			Х											
123	X					Х			Х	Х									
127.3	Χ								Х										
131.8		Х	X	X	X	Х													
136.5		Х	Χ	Χ		Х	X	Х		Х									
141.3		Х	X	Х			Х		Х										
146.2		X	X		X	Х		Х	X	\Box									
151.4		Х	Χ		Х					Х									
156.7		X	χ				X	Х											
162.2		Х		X	Х	X		Х	X										
167.9		χ		X		Х	Х	X	X.	Х									
173.8		Х		X			Х	_											
179.9		Х			х		Х	Х	Х	Х									
186.2		х				Х		Х	Х										
192.8			Х	Х	Х	Х	Х	Х											
203.5			Х	Х		Х				Χ.									
210.7			х		X	Х		Х											

THESE INSTRUCTIONS COVER THE FREQ CODING FOR CG MODULE 190429618 USING THE NON STANDARD CG FREQ.

- 1. USE CHART 2 TO CALCULATE THE CG FREQ DESIRED.
- 2. FIND THE FREQ DESIRED BY ADDING UP THE FREQ IN CHART 2.
 ABOVE EACH FREQ IS A CONTACT PIN POSITION NUMBER, IF THIS
 POSITION IS OPEN (THAT IS A PIN IS NOT INSTALLED), THE 6G
 WILL PRODUCE THAT FREQ. IF MORE THAN ONE IS LEFT OPEN, THE
 OUTPUT FREQ WILL BE THE SUM OF THE OPEN POSITIONS.
- EXAMPLE: CG FREQ 128Hz THEREFORE CONTACT PIN POSITION %9
 WILL BE OPEN AND CONTACT PINS WILL BE INSTALLED
 IN POSITION 0, i, 2, 3, 4, 5, 6, 7 AND 8.

 EXAMPLE: CG FREQ 132.75Hz. THEREFORE CONTACT PIN POSITION
 %9 WHICH IS 128, %4 WHICH IS 4, %1 WHICH IS .5,
 AND %0 WHICH IS .25 WILL BE OPEN. ADD THE FREQ
 128 + 4 + .5 + .25 = 132.75. CONTACT PINS WILL BE
 INSTALLED IN POSITION %2, 3, 5, 6, 7 AND 8.
- INSTALL CONTACT PINS, ASSEMBLE COVER AND STAMP LABEL PER INSTRUCTIONS FOR FREQ CODING THE STANDARD CG FREQ.

CHART 2

9	_8	7	6	5	4	3	2	ı	0	CONTACT PIN POSITION
128	64	32	16	8	4	2	1	.5	.25	FREQ IN Hz

(19D900782, Sh. 4, Rev. 0)

	OCTAL CODES										
PRIMARY CODE	EQUIVALENT CODE	PRIMARY CODE	EQUIVALENT CODE	PRIMARY CODE	EQUIVALENT CODE						
023	340, 766	205	135, 610	464	237, 642, 772						
025		223	350, 475, 750	465	056, 656						
026	566	226	104, 557	466	144, 666						
031	374, 643	243	267, 342	503	157, 312						
032		244	176, 417	506	224, 313, 574						
043	355	245	370, 554	516	067, 720						
047	375, 707	251	236, 704, 742	532	161, 345						
051	520, 771 .	261	227, 567 ⁻	546	317, 614, 751						
054	405, 675	263	213, 136	565	307, 362						
065	301	265	171, 426	606	153, 630						
071	603, 717, 746	271	427, 510, 762	612	254, 314, 706						
072	470, 701	306	147, 303, 761	624	075, 501						
073	640	311	330, 456, 561	627	037, 560						
074	360, 721	315	321, 673	631	231, 504, 636						
114	327, 615	331	372, 507	630	745						
115	534, 674	343	324, 570	632	123, 657						
116	060, 737	346	616, 635, 724	654	163, 460, 607						
125	172	351	353, 435	662	363, 436, 443 444						
131	572, 702	364	130, 641	664	344, 471, 715						
132	605, 634, 714	365	107	703	150, 256						
134	273	371	217, 453, 530	712	136, 502						
143	333	411	117, 756	723	235, 611, 671						
152	366, 415	412	127, 441, 711	731	447, 473, 474 744						
155	233, 660	413	133, 620	732	164, 207						
156	517, 741	423	234, 563, 621 713	734	066						
162	416, 553	431	262, 316, 730	743	312, 515, 663						
165	354	431	276, 326	743 754	076, 203						
172	057	445	222, 457, 575	104	0,0, 203						
174	142, 270	440	222, TOI, 010								

Table 1 - Primary and Equivalent Octal Codes

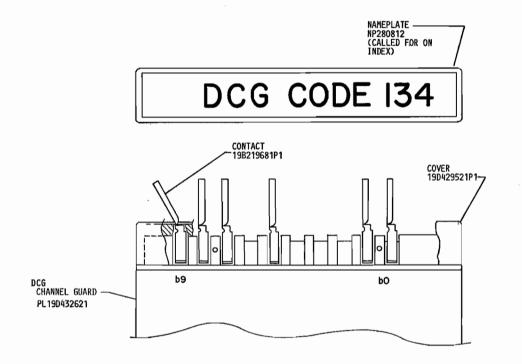
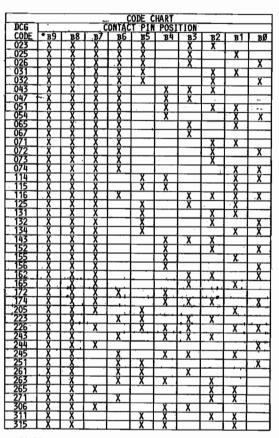
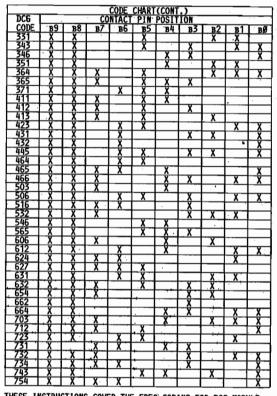


FIG. 2



* B9 IS LEFT OPEN IN 800 MHz RADIOS



THESE INSTRUCTIONS COVER THE FREQ CODING FOR DCG MODULI

- INSTALL CONTACT PINS (198219681), PER FIG. 2, IN POSITIONS INDICATED BY "X" IN CHART 1, WHICH AGREES WITH DESIRED DCG CODE. (NOTE - EXAMPLE SHOWN FOR 134).
- 2. ASSEMBLE SNAP ON COVER (19D#29521P
- BREAK OFF CONTACT TABS ABOVE COVER BY BENDING TOWARD EITHE END OF MODULE. (DO NOT BEND TAB TOWARD SIDE OF MODULE).
- I. STAMP APPROPRIATE DCG CODE ON LABEL (NP280812) AND ASSEMBLE IN RECESS ON TOP OF COVER. (EXAMPLE 134).

RC4235A